

RPC based Semi-Digital HCAL with an embedded readout

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UR



Overview

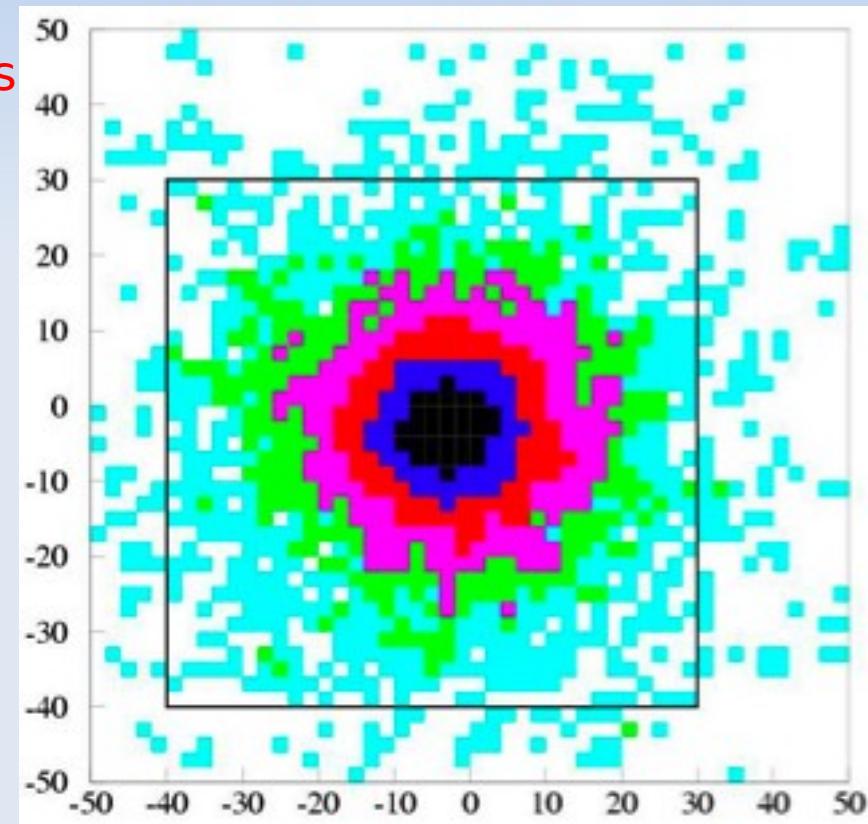


- Case for a digital calorimeter
 - Detectors :
 - ▶ RPC, MGRPC
 - ▶ μ MEGAS, GEMs
 - Digital Readout by embedded ASICs
 - ▶ HARDROC
 - ▶ DIRAC
 - Integration & Debug Card:
DHCAL1 & readout
 - Cosmic tests
 - Beam tests
-
- 1 m² prototype
 - ▶ Validation of large surface detector & readout
 - 1 m³ prototype
 - ▶ First use of 2nd gen DAQ
 - ◆ see V. Bartsch talk
 - *Efforts of integration in ILD & SiD*
 - ▶ *Mechanical & simulation*

Case for a Digital HAdronic CALorimeter



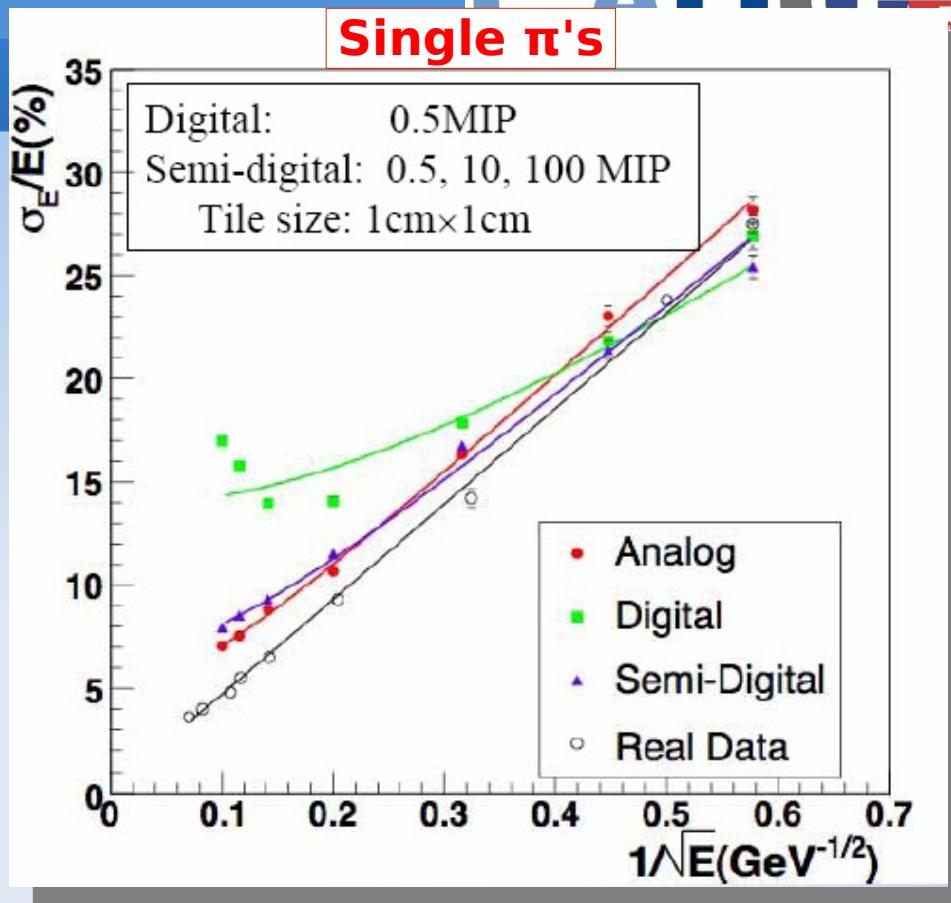
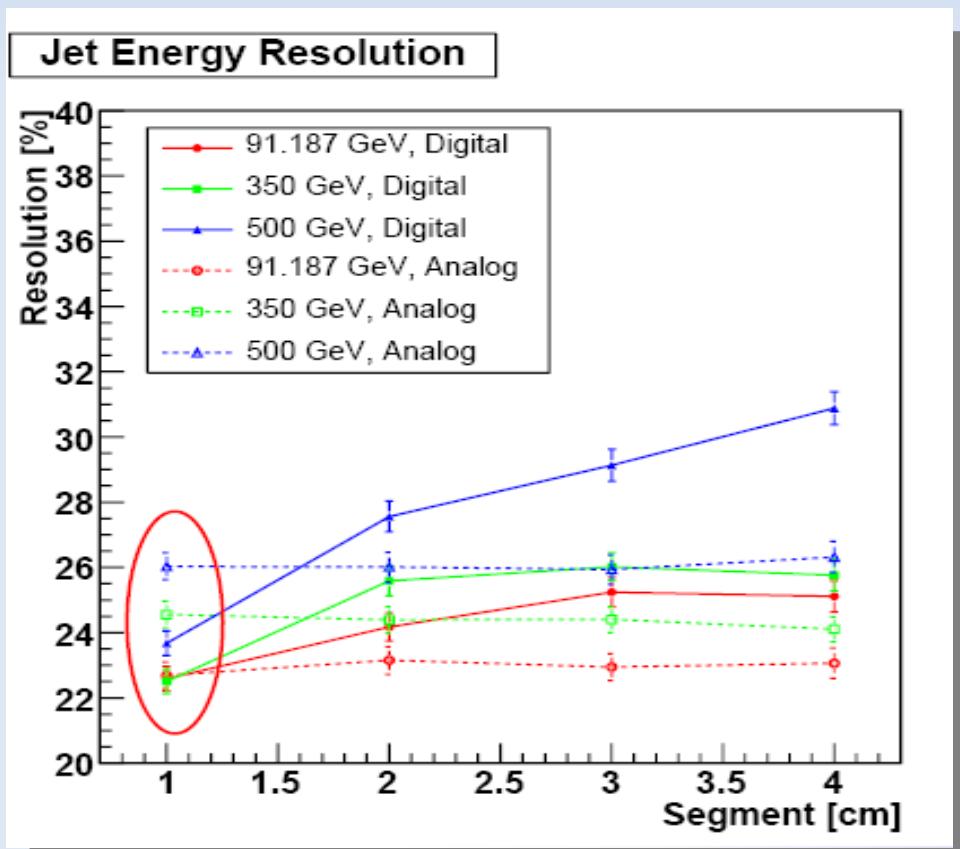
- 1 or 2 bits of information per cell
 - ▶ Finer granularity → $1 \times 1 \text{ cm}^2 \times 48 \text{ planes}$
 - ◆ Ideal for a **PFA** approach
 - ▶ Cheaper, simpler, more robust detectors
 - ◆ GRPC, MGRPC, μ MEGAS, GEM's
- Gaseous detectors
 - ▶ insensitivity to neutrons
 - ◆ narrower showers (99% of hits in $70 \times 70 \text{ cm}^2$ for 100 GeV π)
 - ◆ suppression of big fluctuations
- Recovery of information
 - ▶ counting
 - ◆ improvement: 3 thresholds
 - ▶ topology
 - ◆ clustering



See note LC-DET-2004-029

Resolution studies

- GLD HCAL study by KEK Group
 - ▶ 3 thresholds (0.5, 10, 100 MIP's)
 - ▶ **$1 \times 1 \text{ cm}^2$ scintillator tiles**
- 1 bit better @ low E



- $e^+e^- \rightarrow qq (\bar{u}d\bar{s})$
 - ▶ $\sqrt{s} = 91, 350, 500 \text{ GeV}$
- Assuming Perfect PFA
 - ▶ Improved jet resolution

H MATSUNAGA
Pramana J. Phys., Vol. 69,
No. 6, December 2007

DHCAL: Gaseous Detectors



- Performance studies
 - ▶ MIP efficiency
 - ▶ Hit multiplicity
 - ▶ Ease of calibration (30 M cells \Rightarrow 30 M elect. channels)
 - ▶ Recovery time (RPC)
 - ▶ Discharge rate (GEM, μ Megas)
 - ▶ Behaviour in hadronic shower (detector & electronics)
 - ▶ Operation in high magnetic field
- Technological challenges
 - ▶ Large surfaces
 - ▶ Thickness
 - ▶ Low cost and industrial process
 - ▶ Aging: no performances degradation

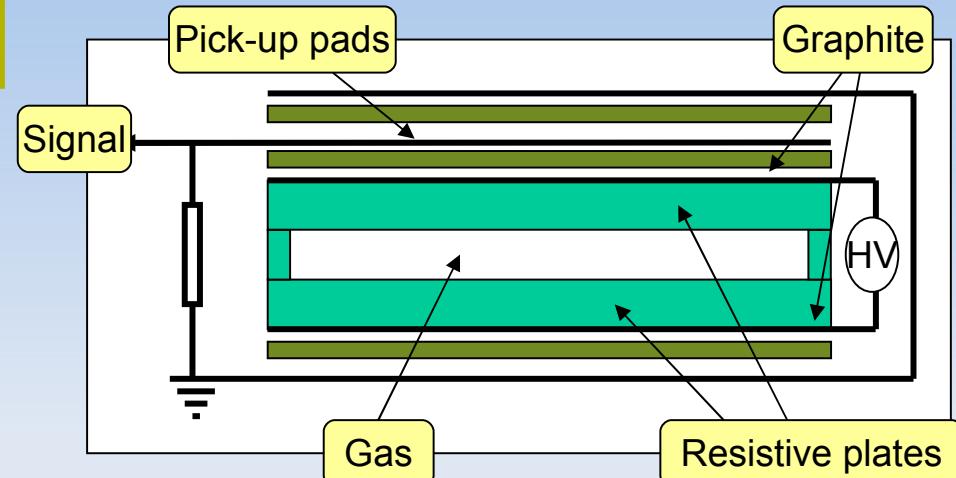
RPC Gaseous detector prototypes



■ GRPC (*IHEP+IPNL*)

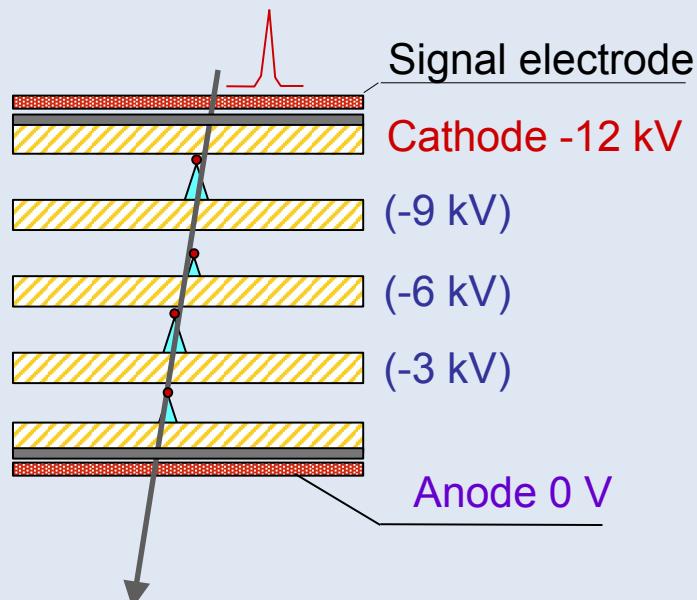
- ▶ simple, robust,
rate $\leq 100 \text{ Hz/cm}^2$
- ◆ 1.2 mm gaz gap
- ◆ 400 μm glass plate
- ◆ Graphite/Licron/Statguard
resistive cover
- ◆ $\sim 7.4 \text{ kV}$

TFE	93%
Isobutene	5%
SF6	2%



■ Multi-gap RPC (*INFN Bologna-CERN*)

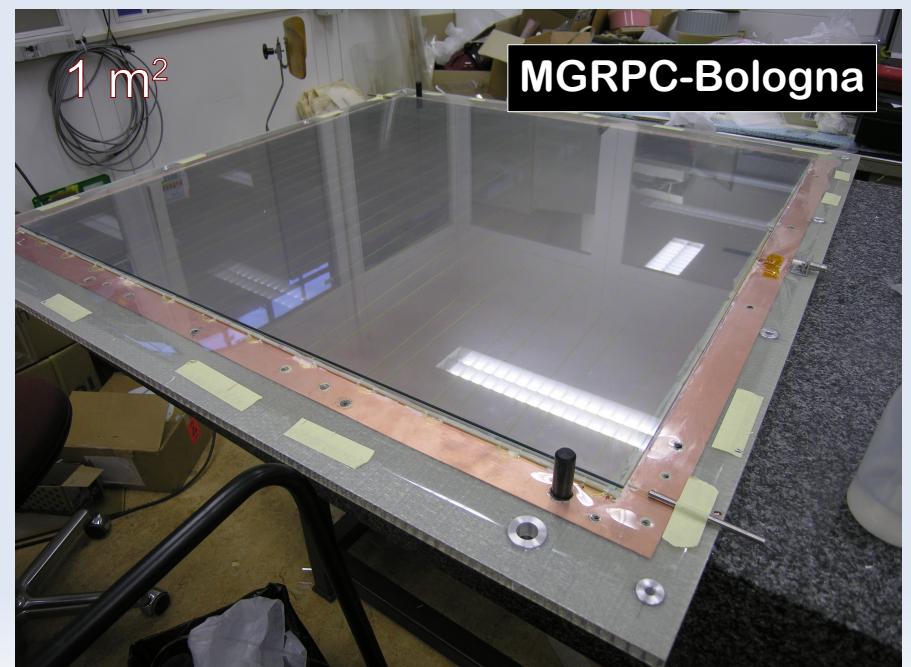
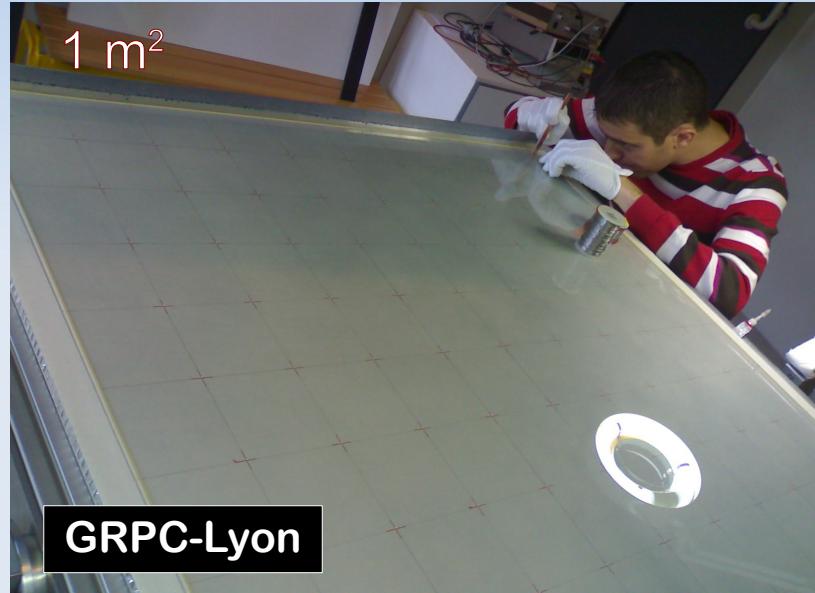
- ▶ Higher rates & efficiency
- ▶ Idem Alice ToF system
- ◆ 4 x 250 μm gaz gaps
- ◆ 400 μm inner glass plates
- ◆ 550 μm ext. glass plates
- ◆ $\sim 10\text{--}12 \text{ kV}$



Small & large prototypes

■ GRPC:

- ▶ $8 \times 8, 32 \times 8, 50 \times 32, 100 \times 32, 100 \times 100$
 1 cm^2 -pad : already produced and tested.



■ MGRPC

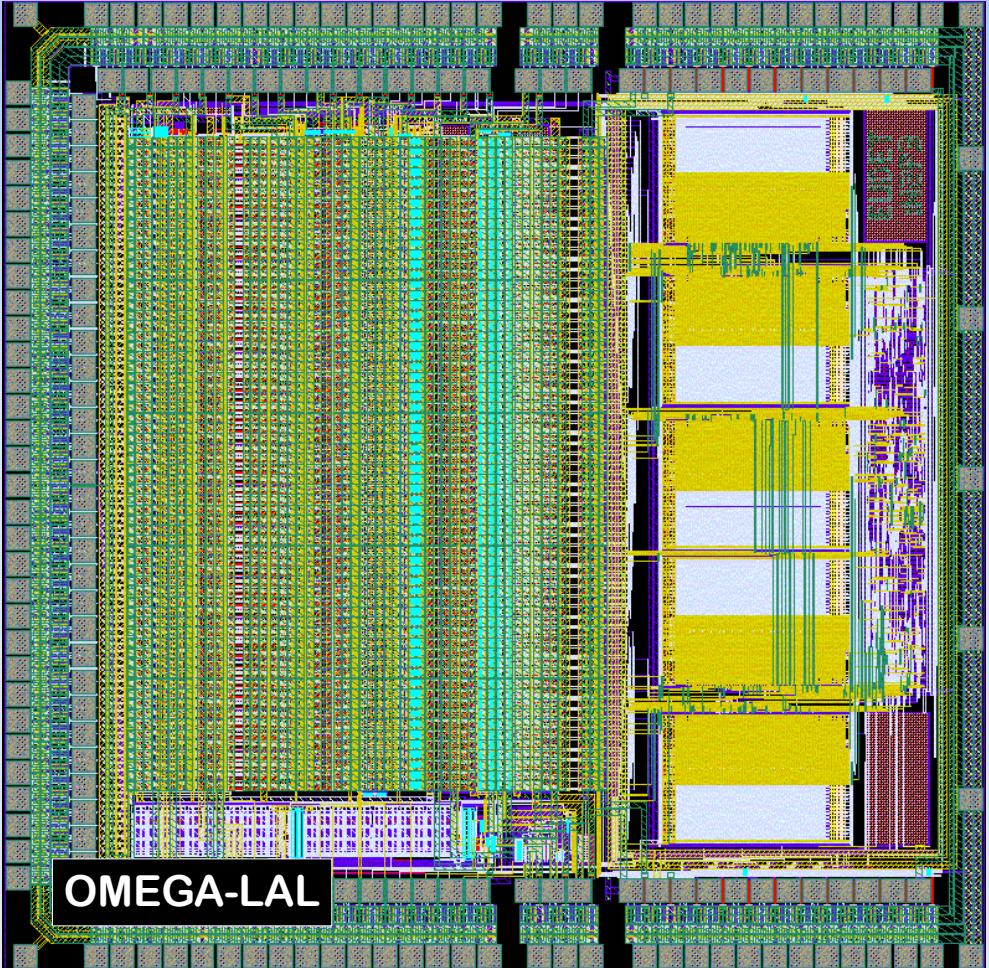
- ▶ 32×8 , produced & tested
- ▶ 100×100 under development

improve on gas distribution system, spacers and
resistive painting, dead zones

HarDROC (Hadronic RpC Detector Read Out Chip)



- AMS SiGe 0.35 μ m, 16 mm²
- 64 channels
- Digital/analogue output
- 2 independant thresholds
- low consumption
 - ▶ < 10 μ W/ch
 - ▶ Power pulsing
- Digital memory
 - ▶ 128 events
 - ▶ ASIC ID (8b), BC ID (24b), hits
- Large gain range (6bits)
 - ▶ Channel wise
- X-talks < 2%
- Threshold > 10 fC



* DIRAC: Another ASIC developed in IPNL/LAPP
aims at a threshold of 3 fC

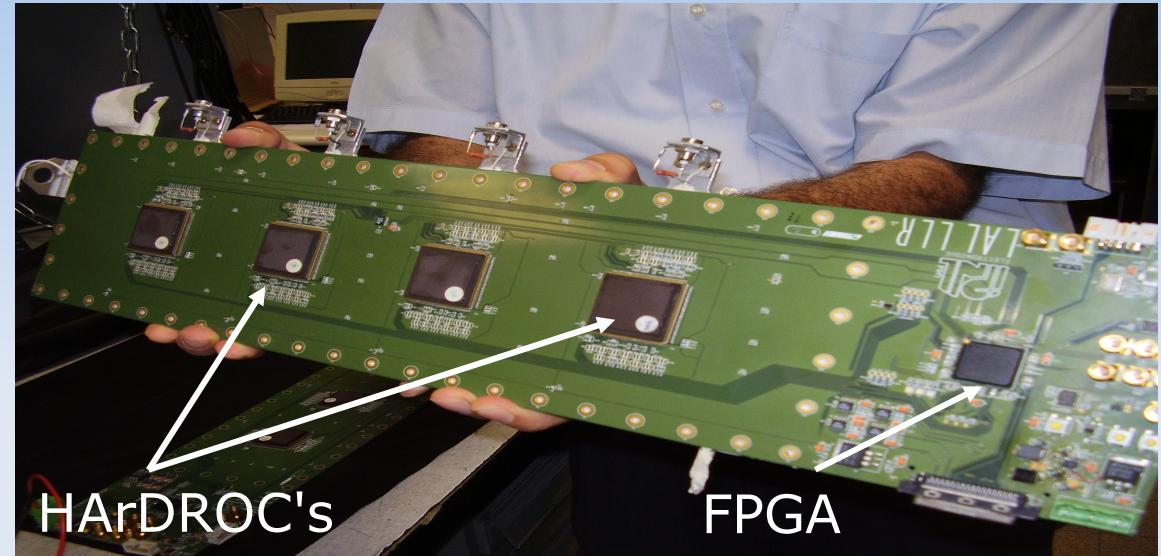
- First batch (460 chips) produced and being tested
 - ▶ Will be used for the m²
- Correction of the minor bugs of HR1
 - ▶ Mask, memory pointer (dummy frame)
 - ▶ Shift registers improvment (configuration loading)
 - ▶ Bypass on critical signals
- Improvement on Power Pulsing
 - ▶ Now also digital part ⇒ comsumption $\leq 10\mu\text{W}/\text{chan}$
- Dynamic range extension
 - ▶ Gain correction: 8 bits instead of 6
- 3 shapers and 3 threshold (3 indep^t DAC) coded on 2 bits
 - ▶ 10 fC, 100fC, 1pC (for μMEGAS)
 - ▶ 100 fC, 1pC, 10pC (for GRPCs)

Mini DHCAL project



Aim: Validate the new electronics/acquisition scheme for the DHCAL (GRPC/ μMEGAS)

- **8-layer, 800 μ** thick PCB
buried and blind vias
x-talk <0.3 %
- 4 hardroc chips
- Readout **FPGA** → USB
- **8×32** pads detector

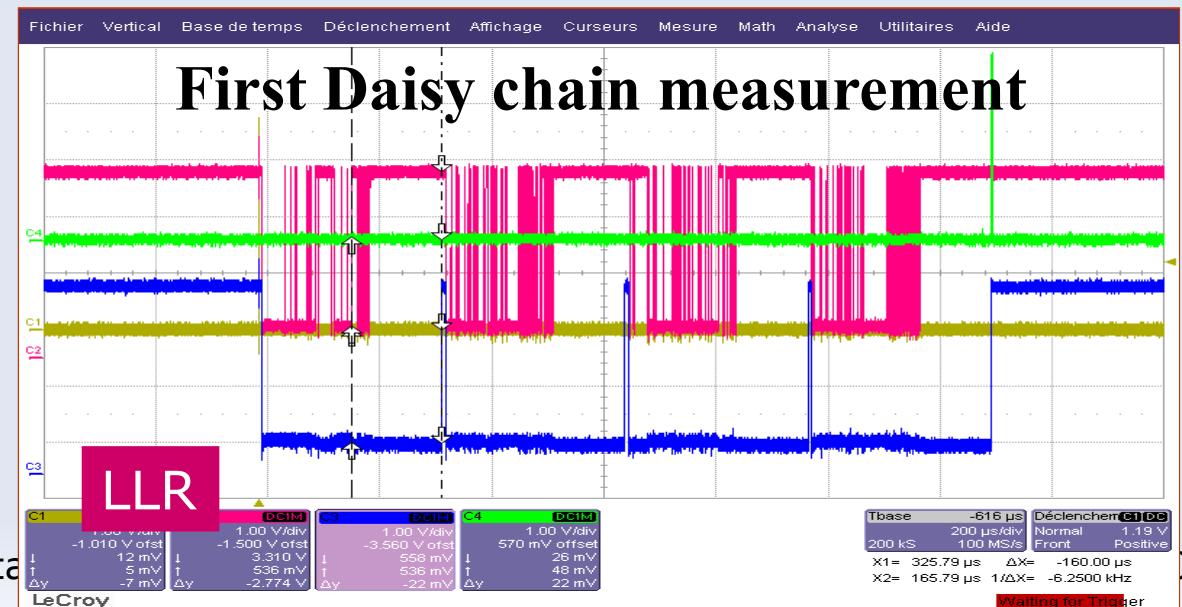


Acquisition modes : different modes are allowed:

a) Train (ILC mode)

b) External trigger :
cosmic rays & test beam

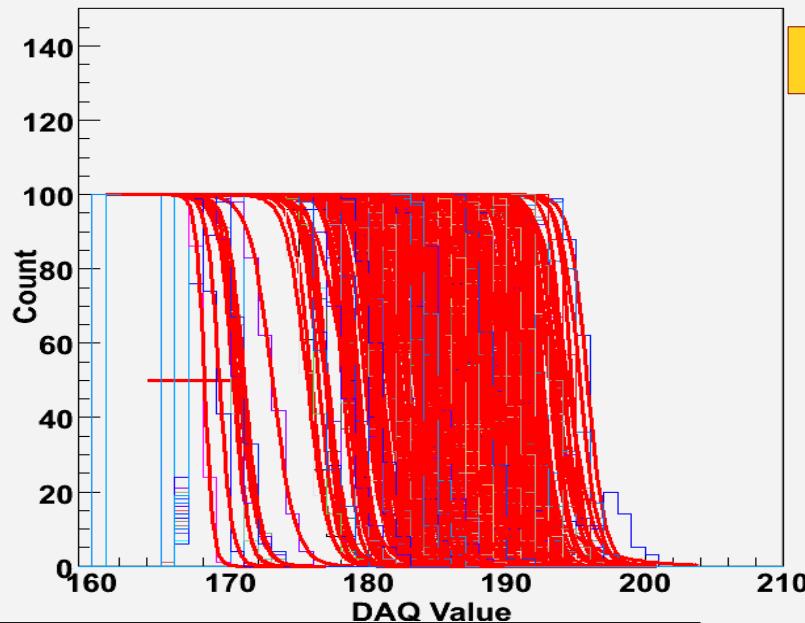
Data output:
digital and analogue



Gain correction

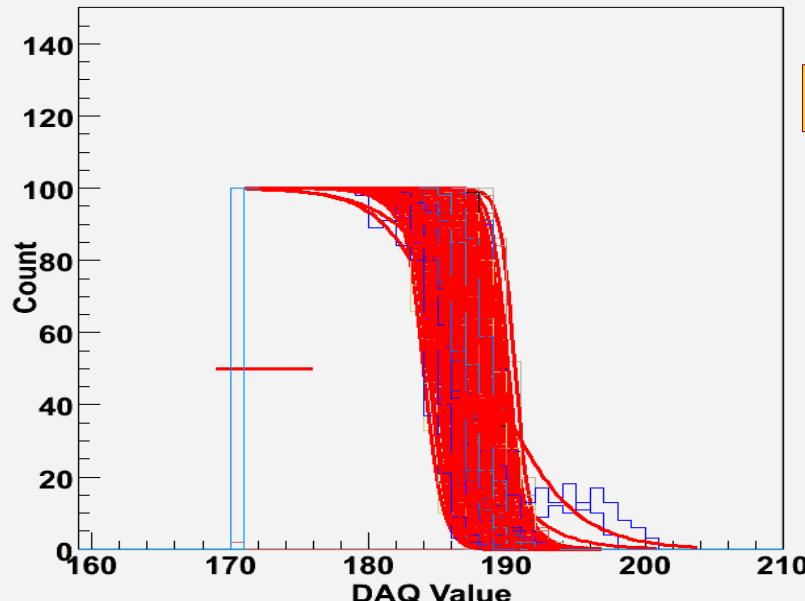


ASIC 1, 2, 3, et 4 Avant Corrections



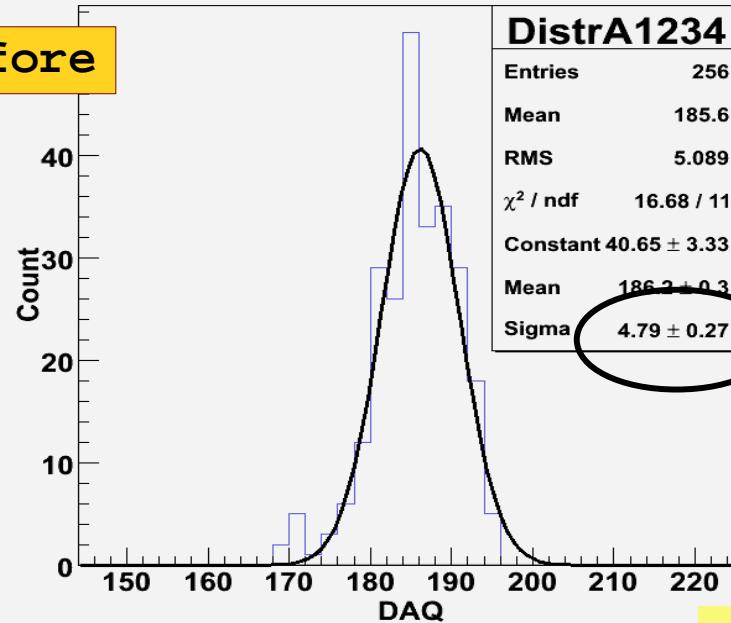
before

Injected charge = 100 fC



after

ASIC 1 2 3 et 4 Distribution des SCurves.

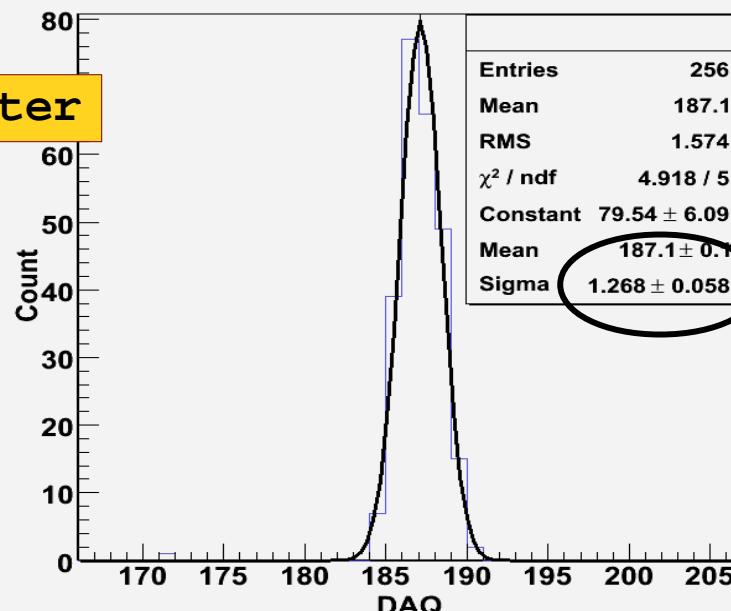


DistrA1234

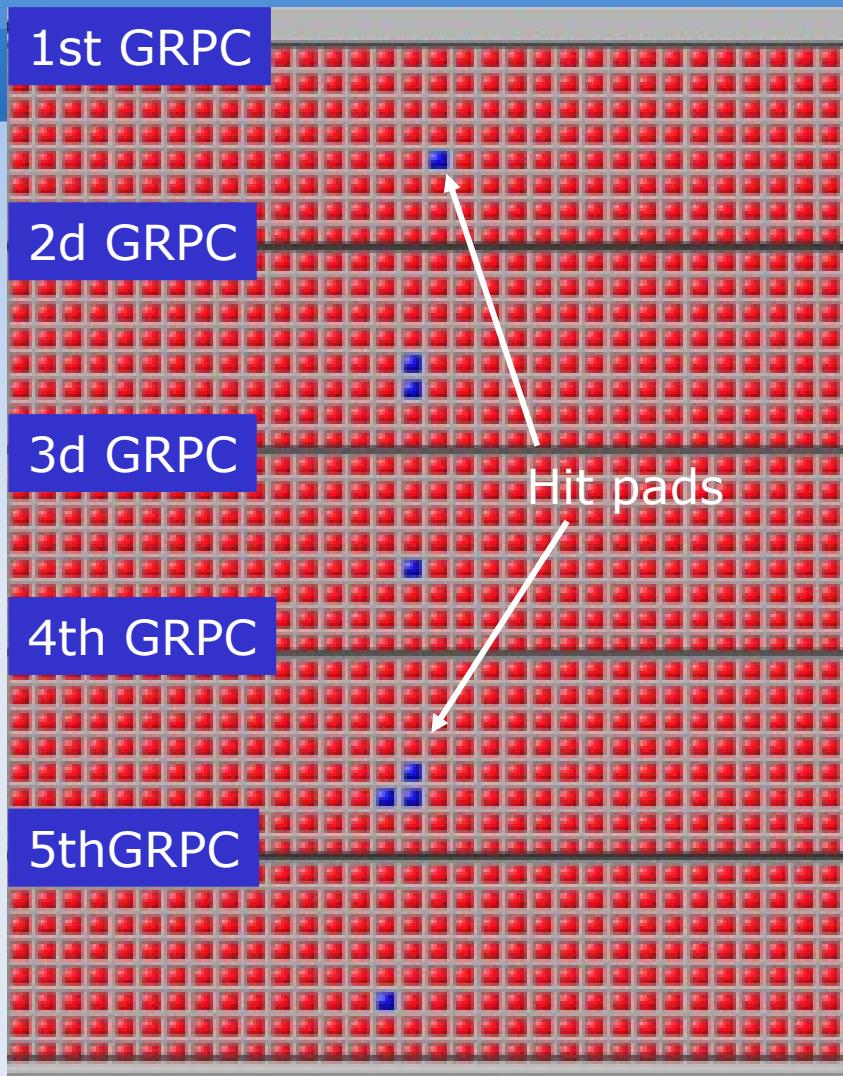
ILC

Reduction:4

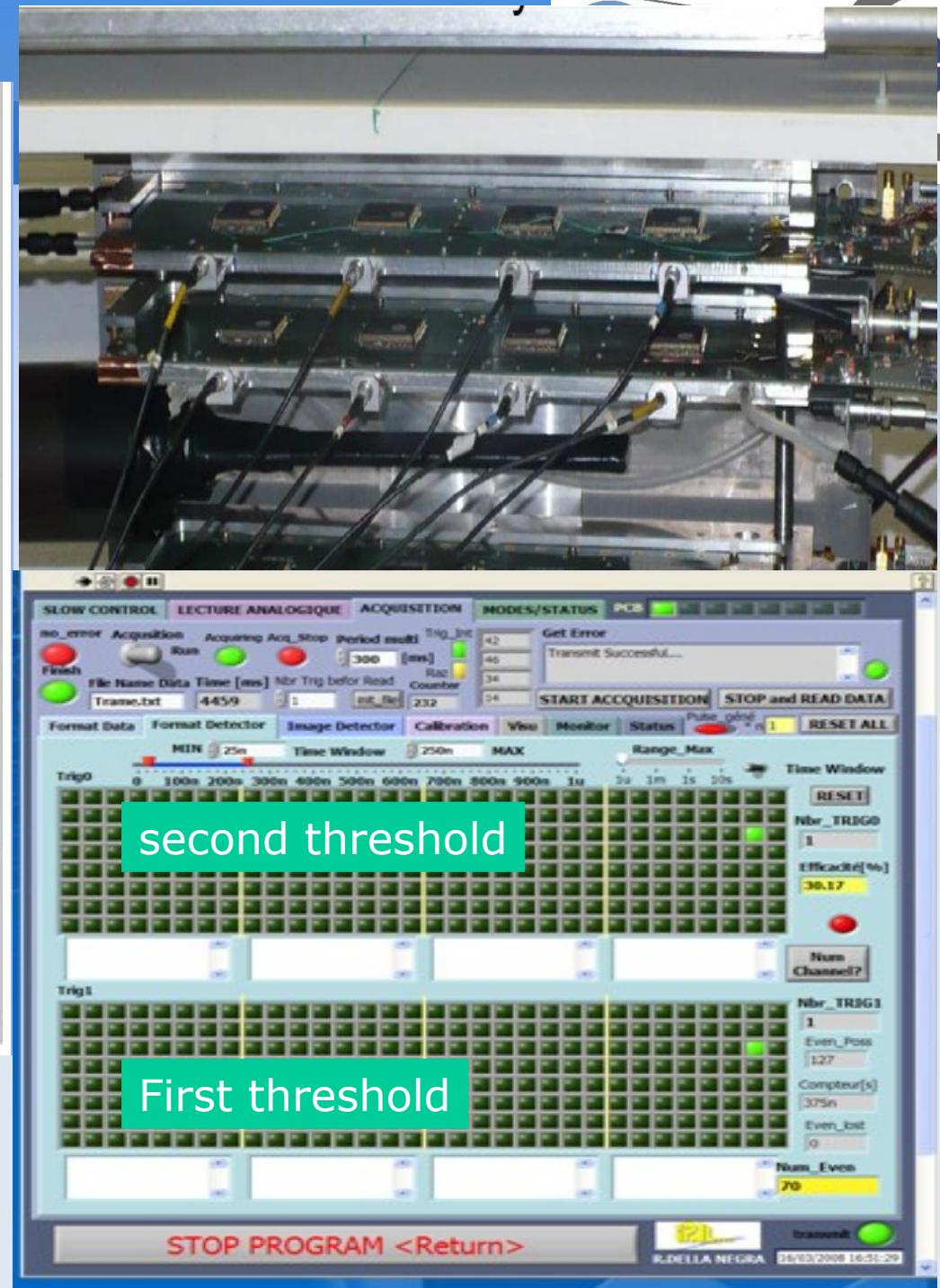
ASIC 1, 2, 3, et 4 Distribution des SCurves Corrigées.



$\approx 2.5 \text{ fC}$



Example of a recorded mip
5-GRPC cosmic rays test bench
Thr. ~ 100fC

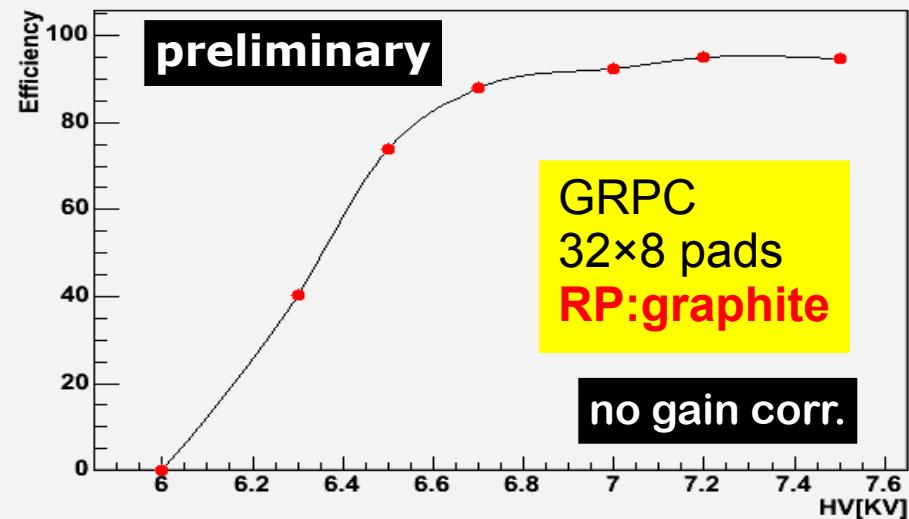


GRPC Efficiency & Multiplicity

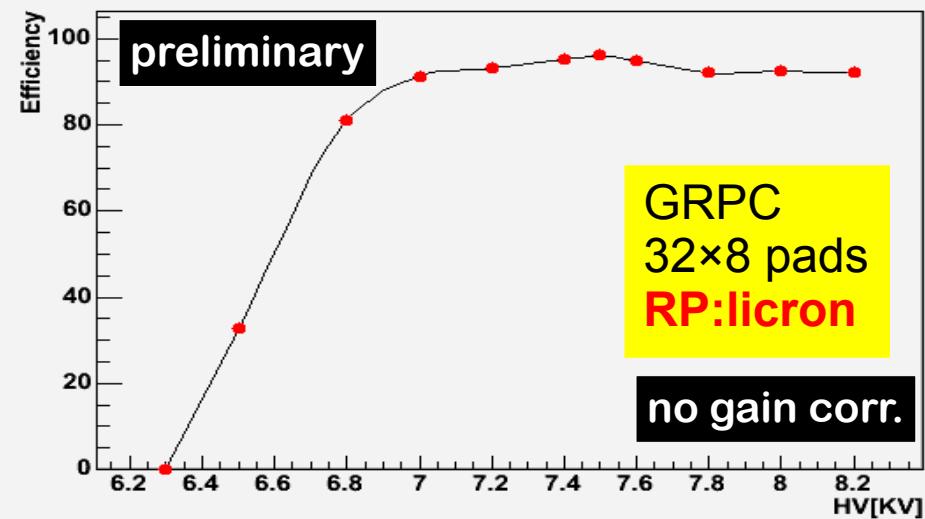
TFE	93%
Isobutene	5%
SF6	2%



Graph

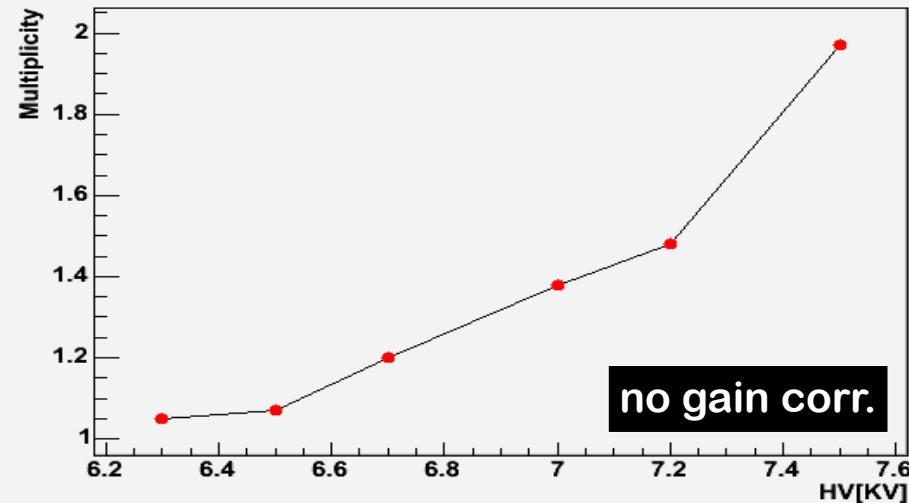


Graph

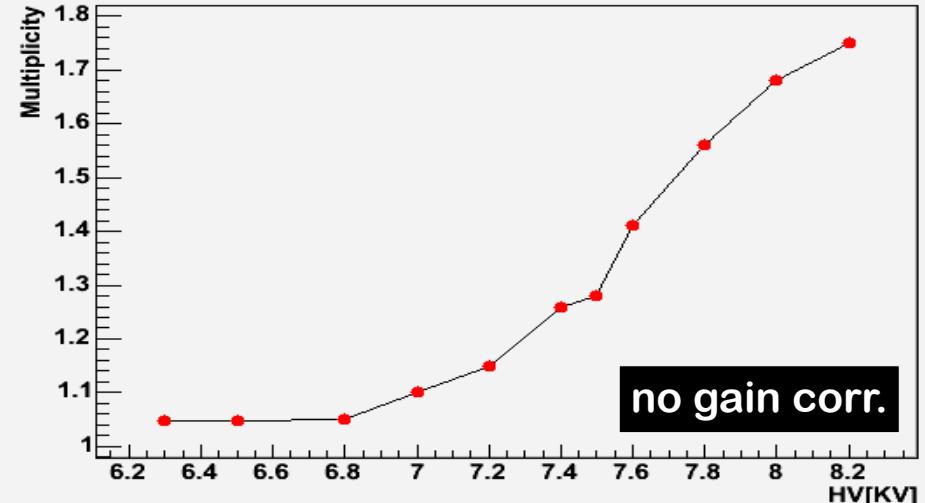


Threshold ≈ 100 fc

Graph



Graph

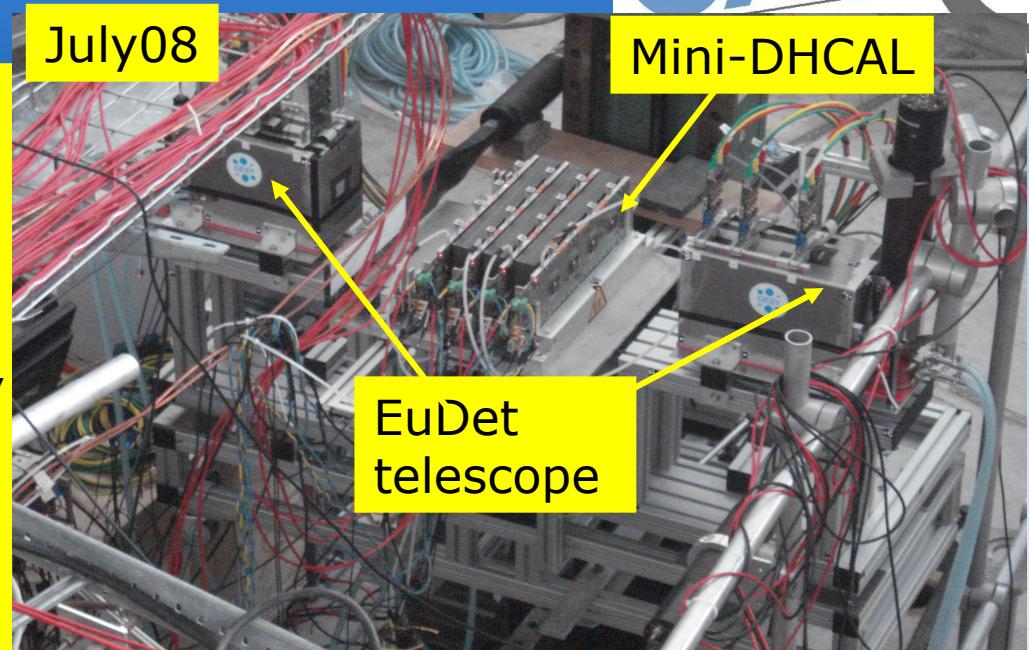


GRPC Mini-DHCAL test at CERN

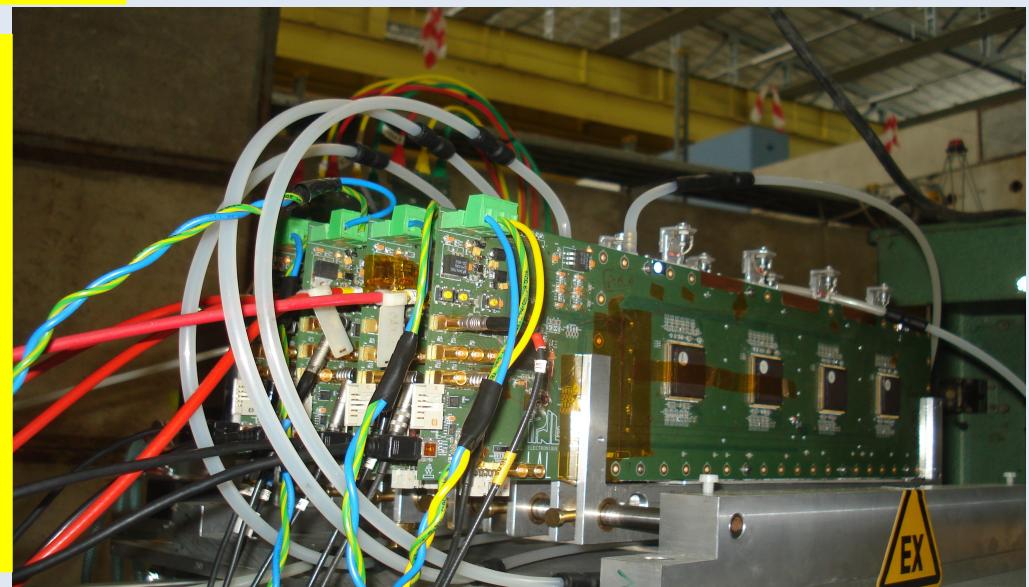


Aim:

- Validate the whole electronics readout system in beam conditions
- Study the GRPC behavior vs (HV, thresholds, angle, position, rate)
- Study the first phase of the hadronic shower (pion energy 1-12 GeV)



- About 400 k evts were collected (DAQ rate : 20 Hz) and being analyzed
- The readout system as the GRPCs performed very well: stability and efficiency



Beam test periods



PS: Mostly π (3-12 GeV) + few μ , very few e^-

PS T10 17—24 july with the EUDET telescope: $\sim 260k$ trig evts

- With EUDET Pixel Telescope: $7 \times 7 \text{ mm}^2$ active sensors
- **Angle & position** scans
- Other data: trigger large scintillators ($10 \times 40 \text{ cm}^2$)

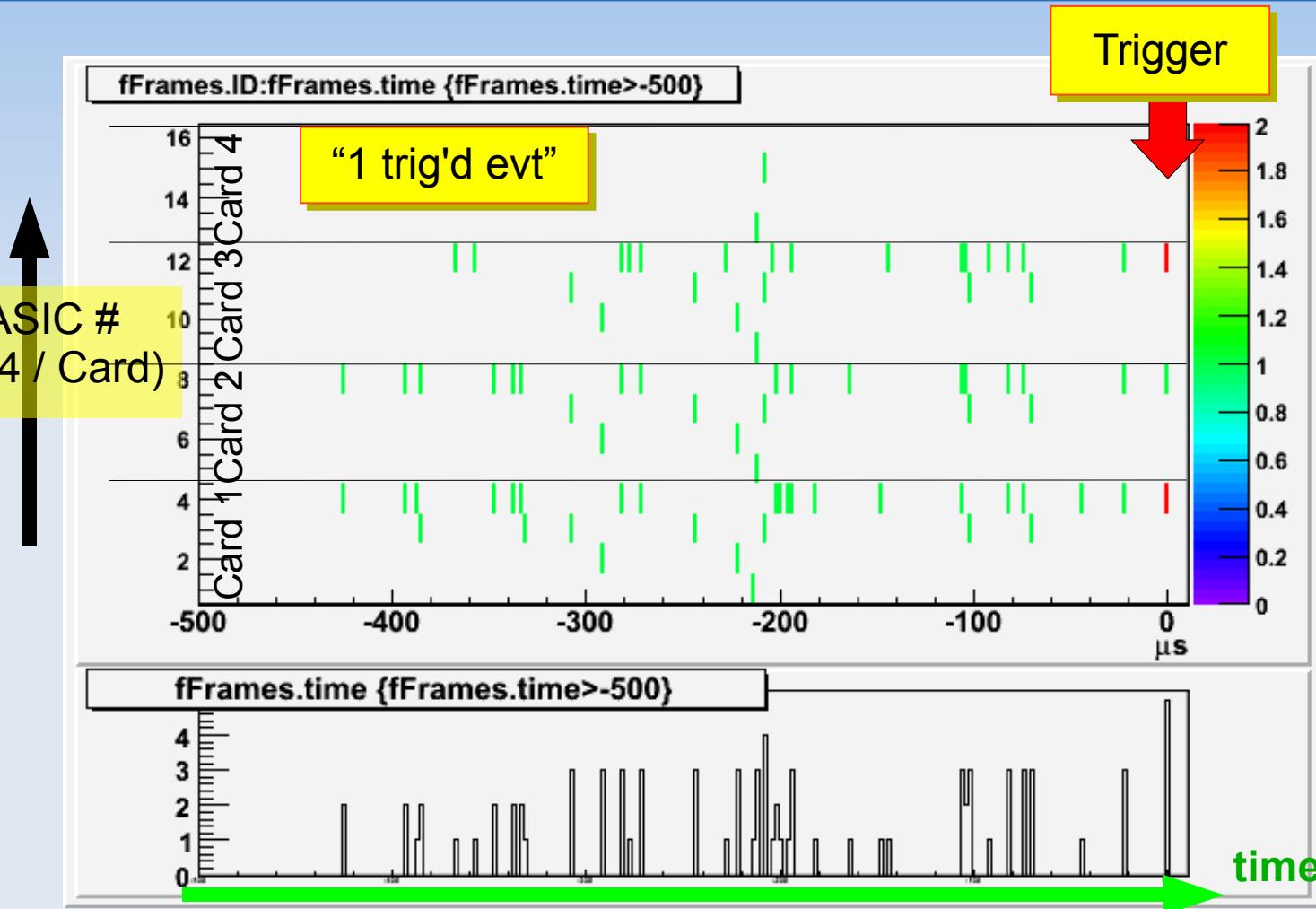
PS T9: 28/07 — 04/08 $\sim 80k$ trig evts

- Complement Pion data with 2λ of W, **angular** scan
- Analogue readout of 1 chamber
- Test of a wide RPC: $100 \times 35 \text{ cm}^2$ (readout with 4 PCB $\Rightarrow \sim 32 \times 32 \text{ cm}^2$)

PS T9: 07/11 — 12/08 $\sim 65k$ trig evts

- Shared test with μ Megas (\neq set-up)
- Complement test: **HV** scan, **thr.** Scan, **CO2** (as repl. of Isobutane), **Beam intensity** scan
- **Tentative:** m^2 + 24 HR1 PCB + new DAQ elec & soft (DIF)

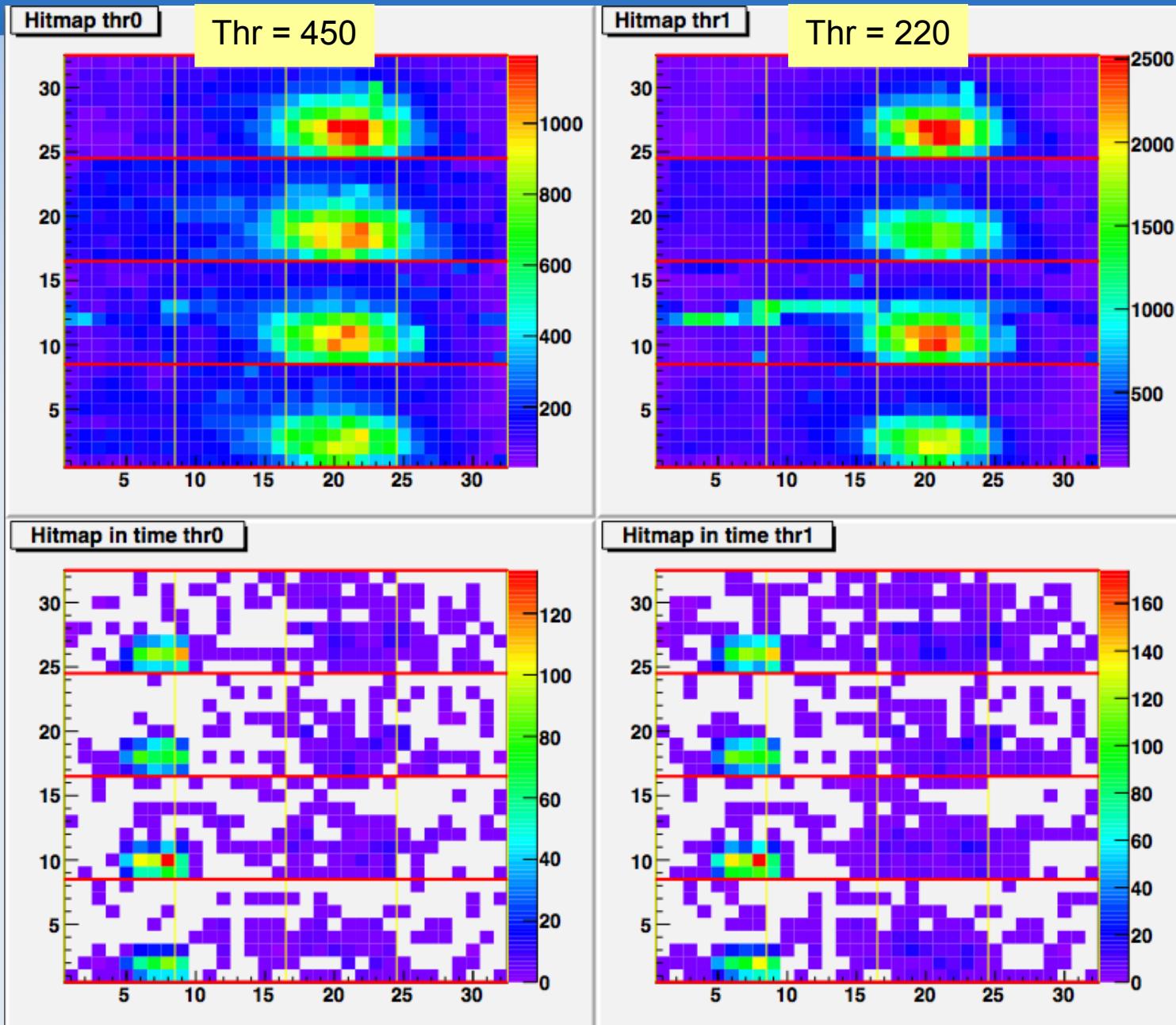
Timing: single event + auto-trig



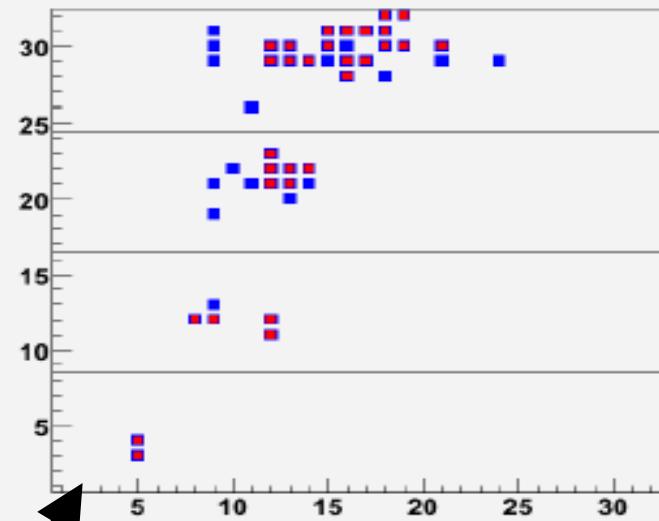
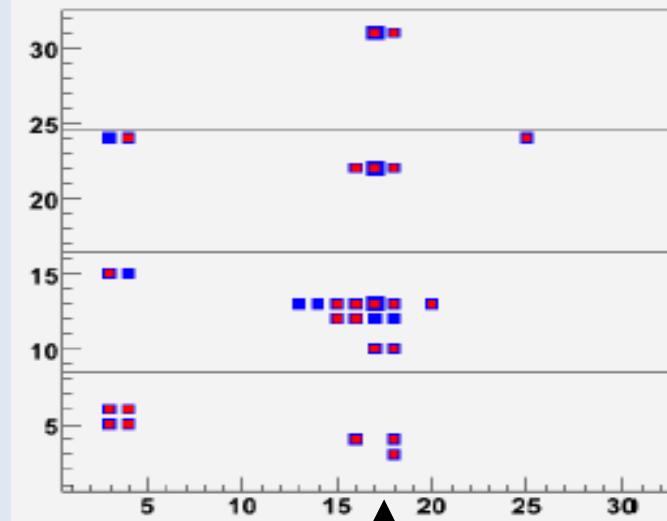
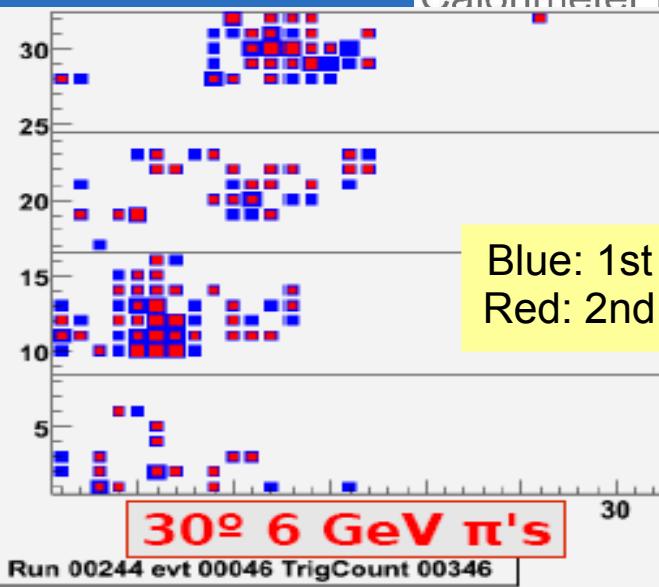
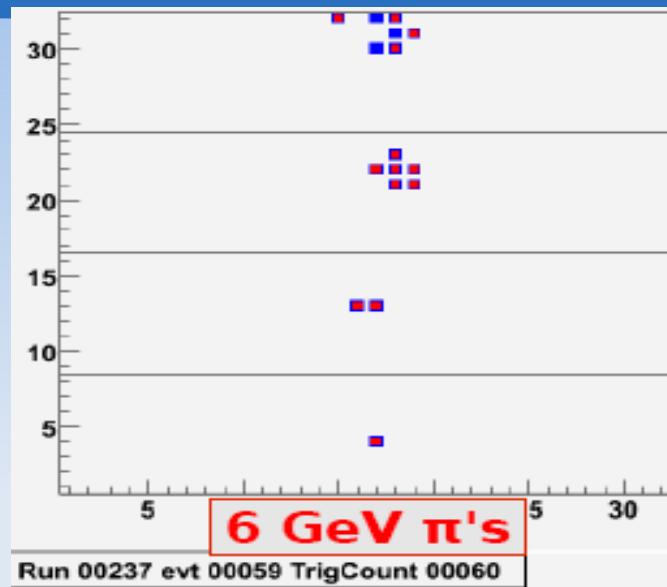
Many More stat Available with proper time reconstruction
Expt'd: 830

- CERN PS: **400 ms** spills every 48 or 33s (day/night cycles).
- Running mode: **single event with auto trig**
+ BUSY logic & automatic RAMFULL recovery (\Rightarrow BUSY signal)

First displays

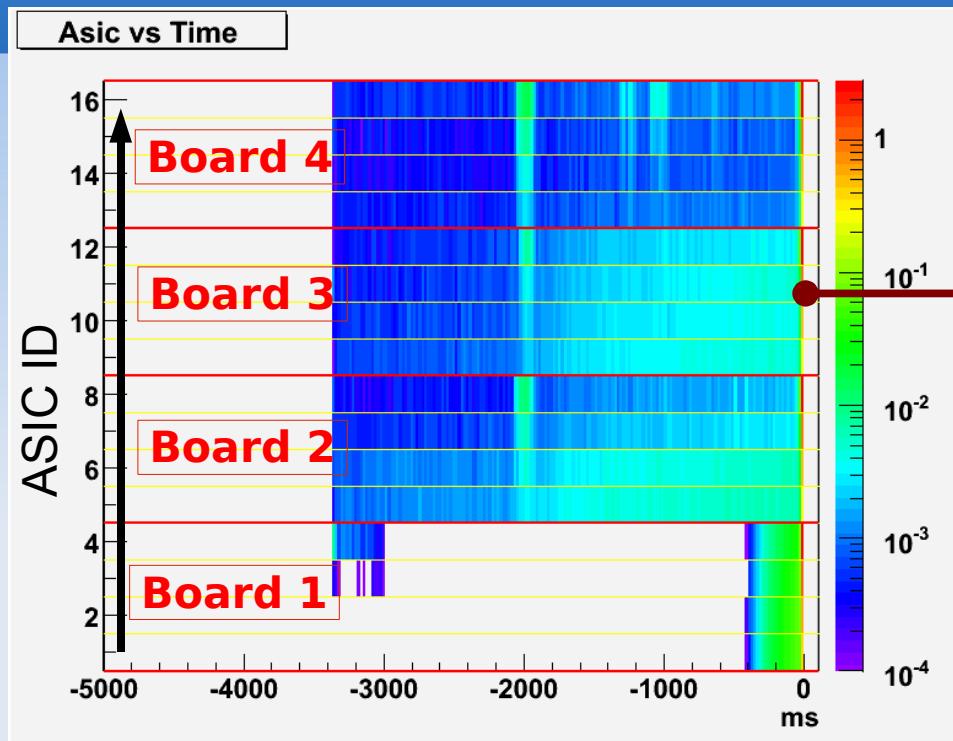


GRPC Mini-DHCAL test at CERN



Beam(pions)

Noise & ROC study



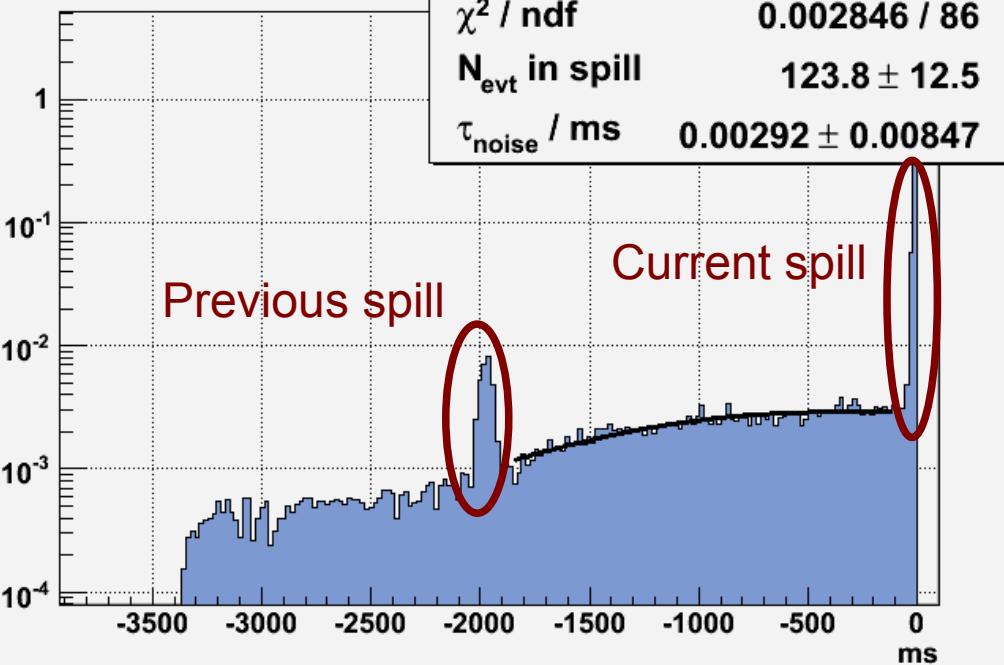
Shape:

- flat noise+event rate τ
- modified by RAMFull (Loss of memory)
- probability at $-t$ =
 - $(1 - P(\text{avail. mem}, t \times \tau))$
 - avail. mem = 128 evts – N_{evt} in spill

$$P(a, x) = \frac{1}{\Gamma(a)} \int_0^x t^{a-1} e^{-t} dt$$

Run00101
Hit rates for each triggered event

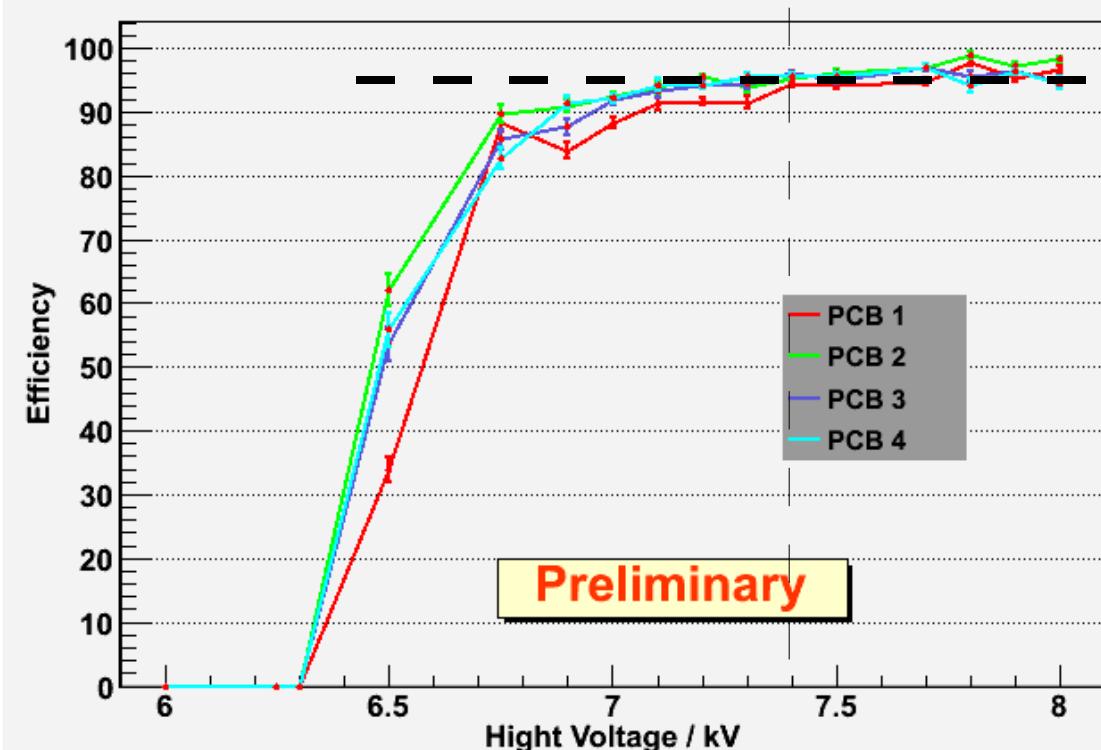
Event time distrib ASIC 12



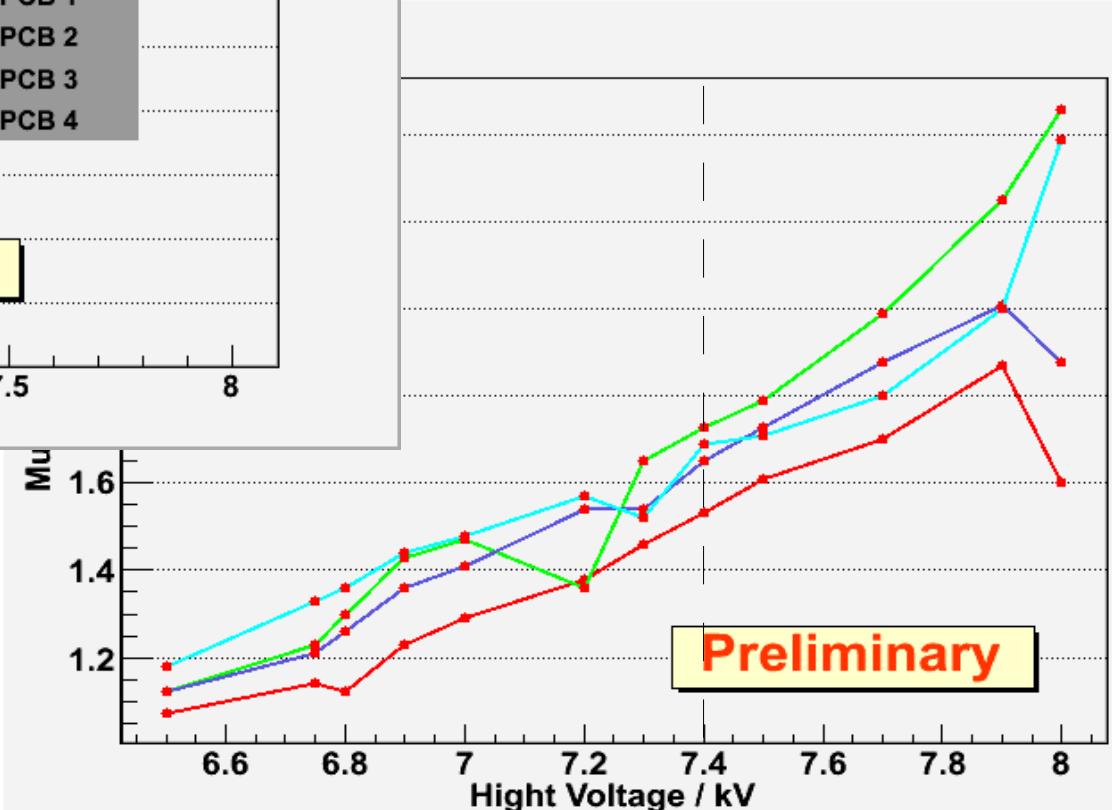
IHEP GRPC: Efficiency & multiplicity



IHEP RPC

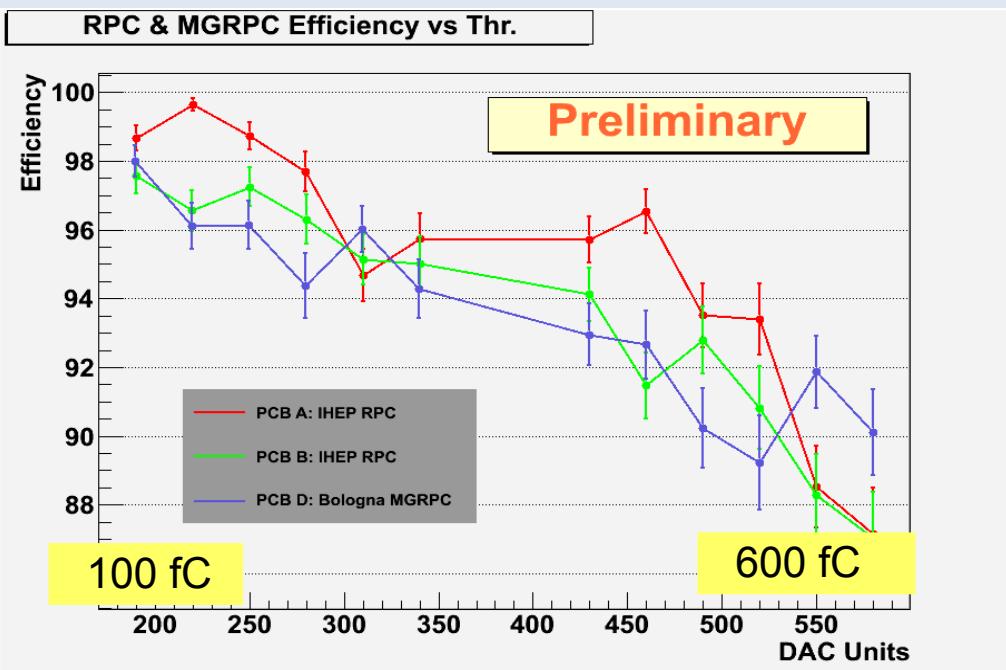
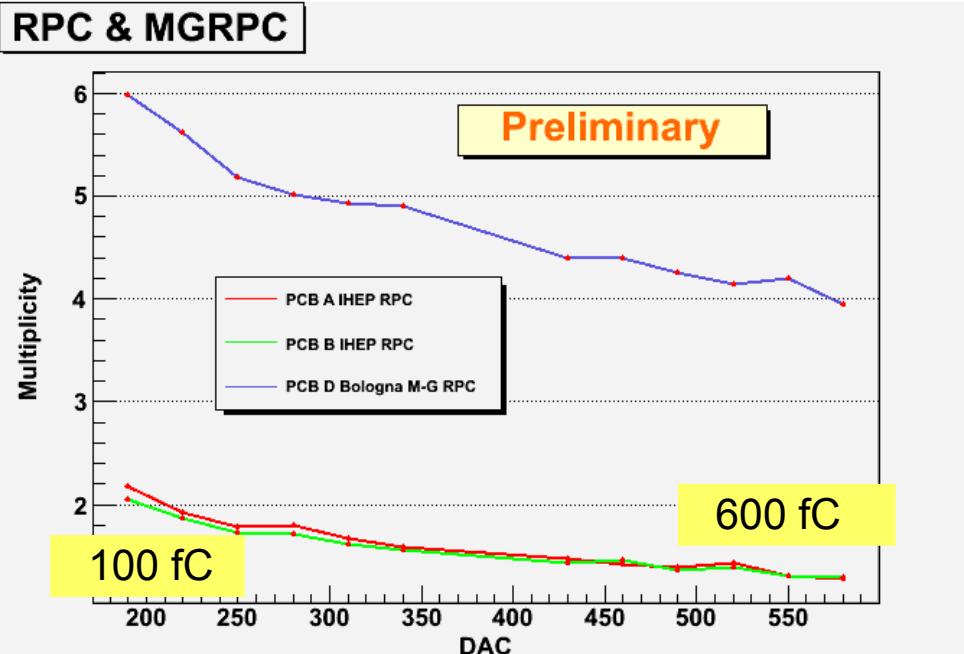
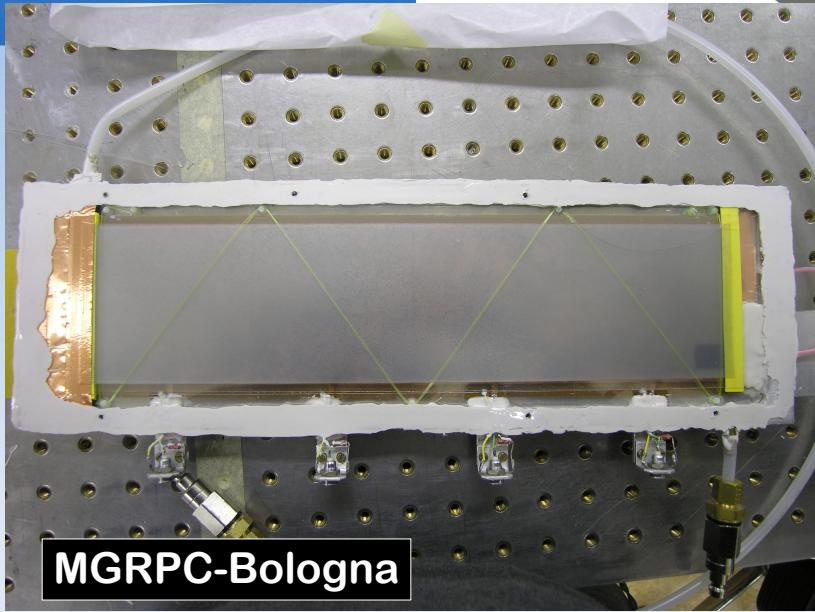
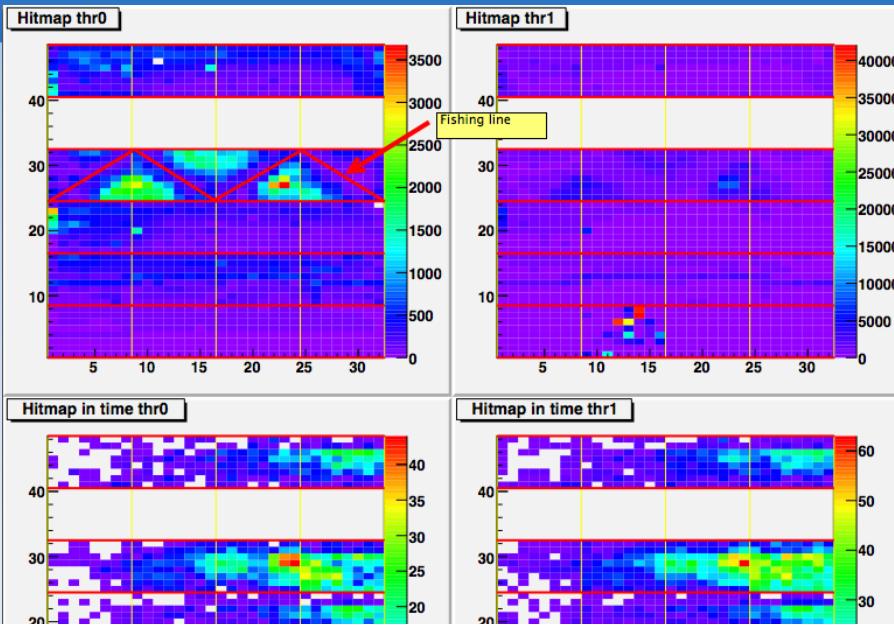


Working point: 7.4 kV
95% efficiency
1.6 pad/track



- Track reconstruction
- Threshold @100fC

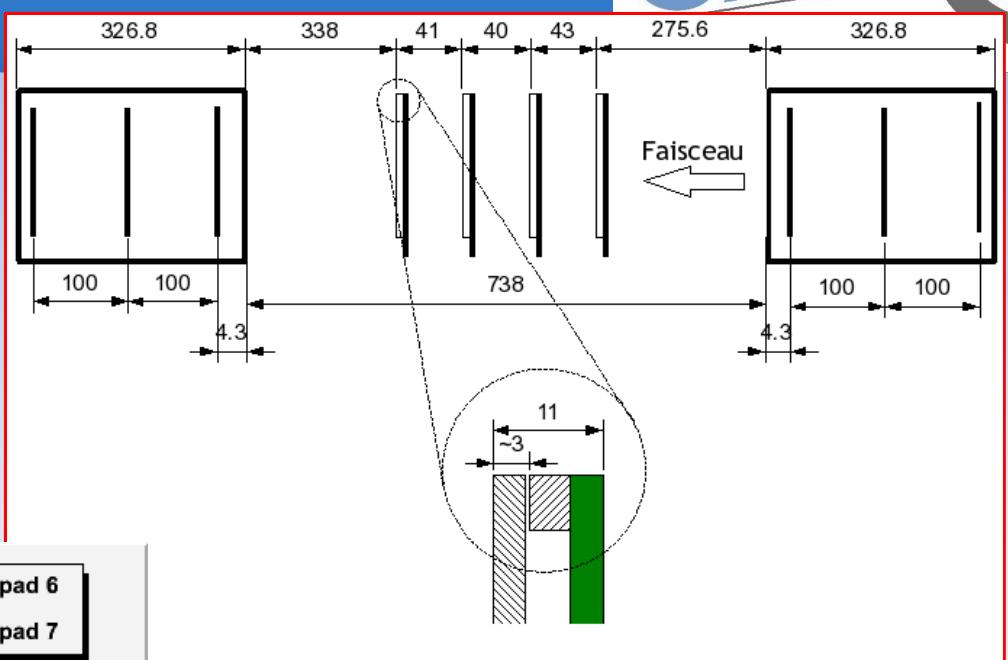
RPC vs. Multi-Gap RPCs



Data with EUDET pixel telescope



- 2 independent DAQ's
 - → Shift of 1 evt
- small surface: $7 \times 7\text{mm}^2$
- Track precision: $\leq 5 \mu\text{m}$



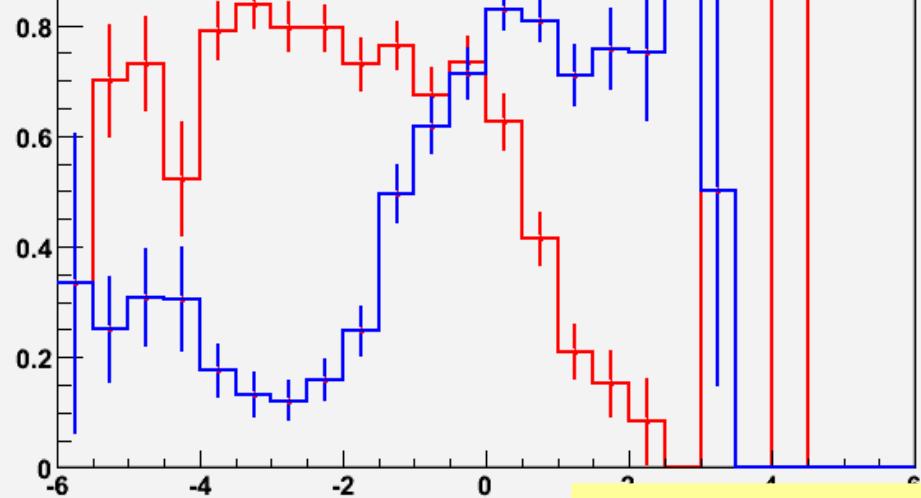
Efficiency of pad 6

Very Preliminary

(multiple track contamination)

Efficiency of pad 6

Efficiency of pad 7



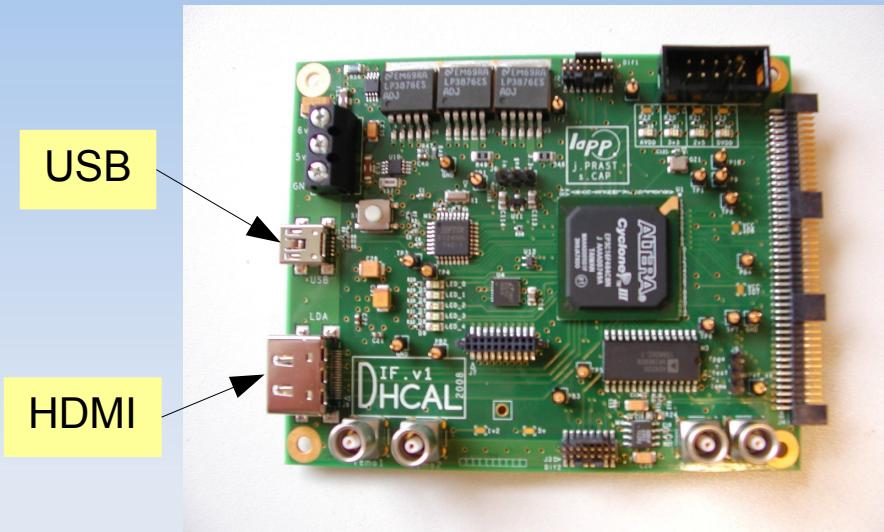
X tracks projected on PCB/mm

Clean-up (multiple tracks, multiple hits) and multiple runs analysis on going....

The 1 m² project

DIF

- 10-layer board (6 for signals) designed and prototype produced
- FirmWare & SoftWare operationnal and tested in beam (with 4 HR μ Megas card)



ASU

- 8-layer board designed and produced
- $500 \times 33.3 \times 1.2 \text{ mm}^3$
- Connections between adjacent PCB foreseen
- ASICs were tested and plugged

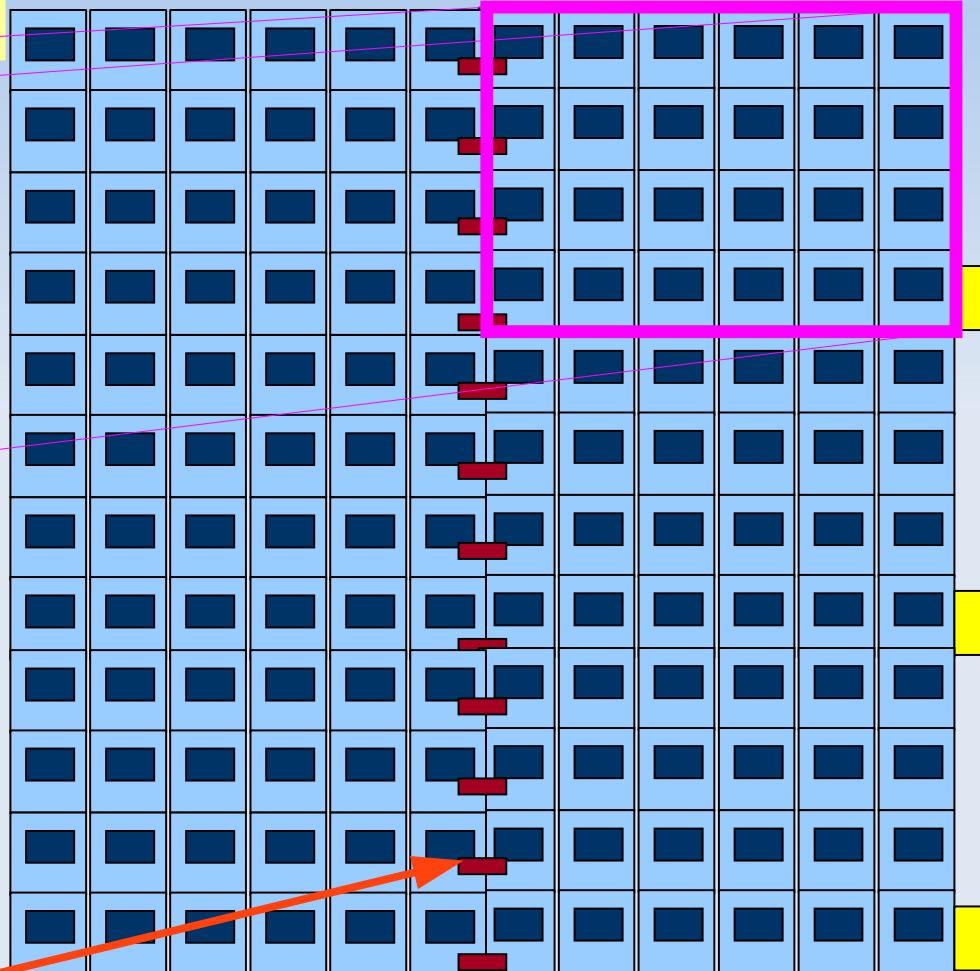
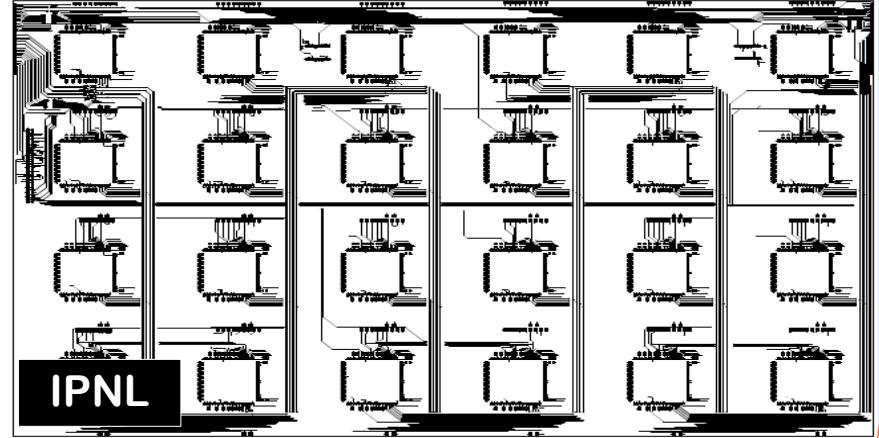
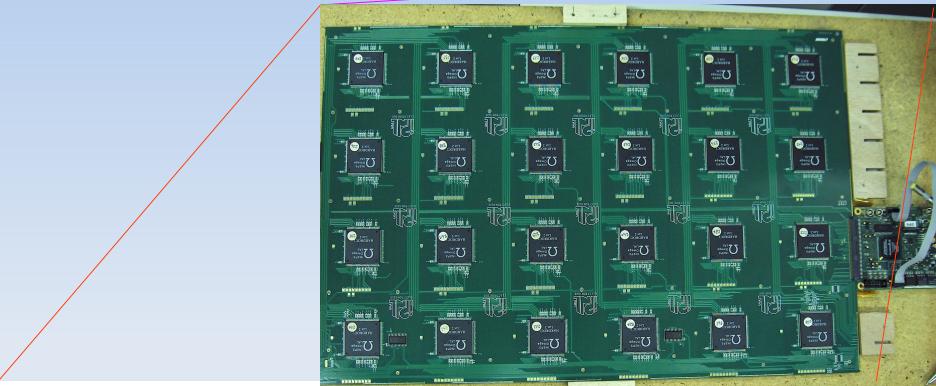


Software

Acquisition software based on US/XDAQ developed

Next steps: m² ASIC support Units

1 ASU → 6×4 chips

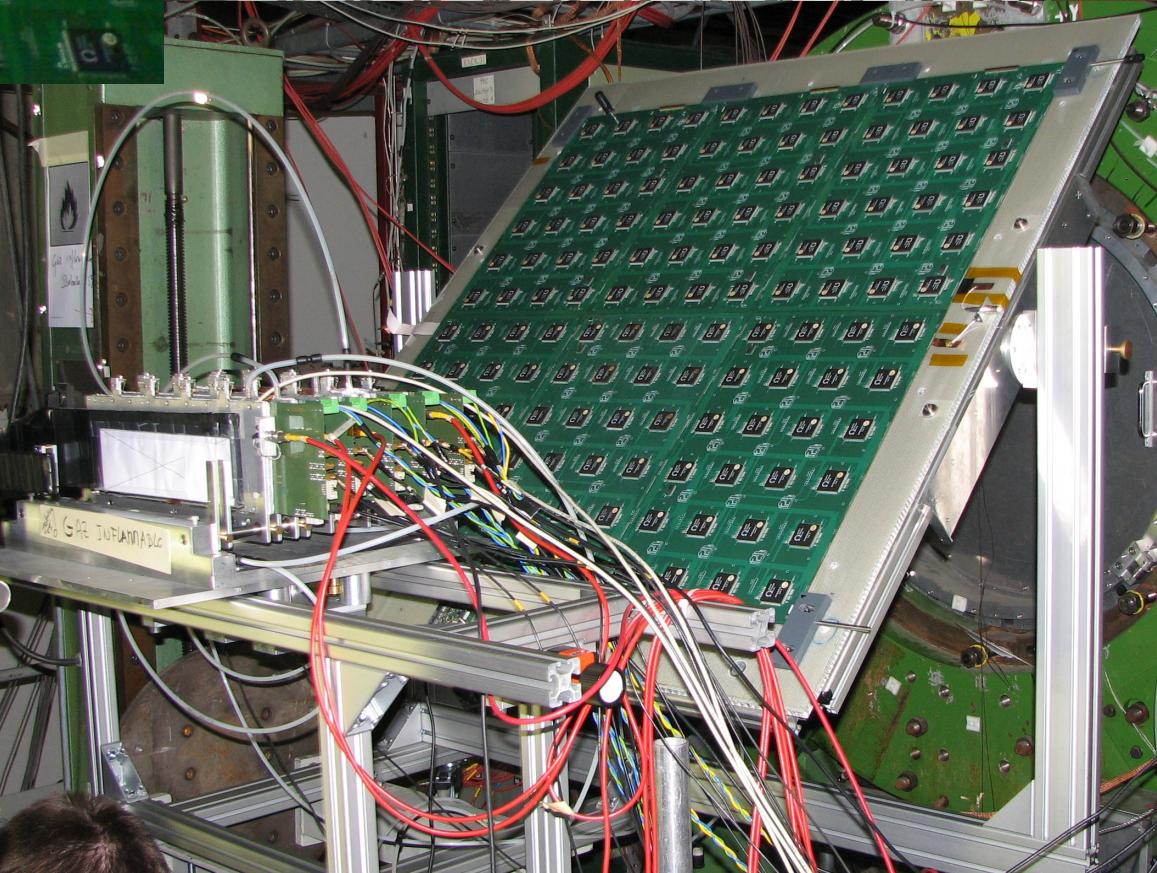


pcb-connector

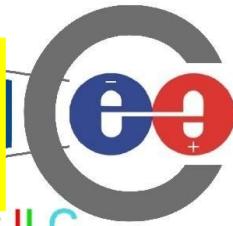
ASU hosting 24 HARDROC chips produced and being tested



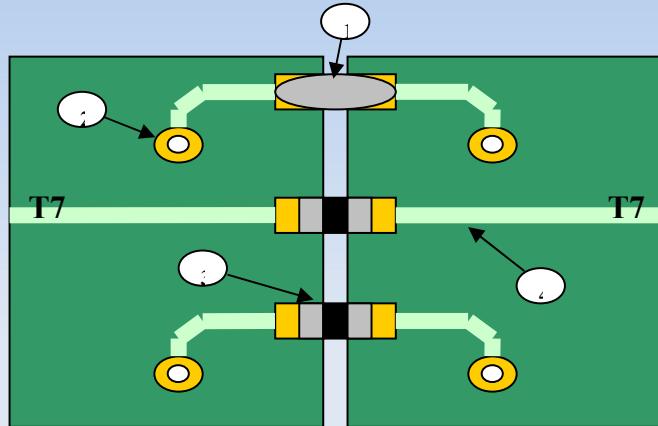
Support is being realized
CIEMAT



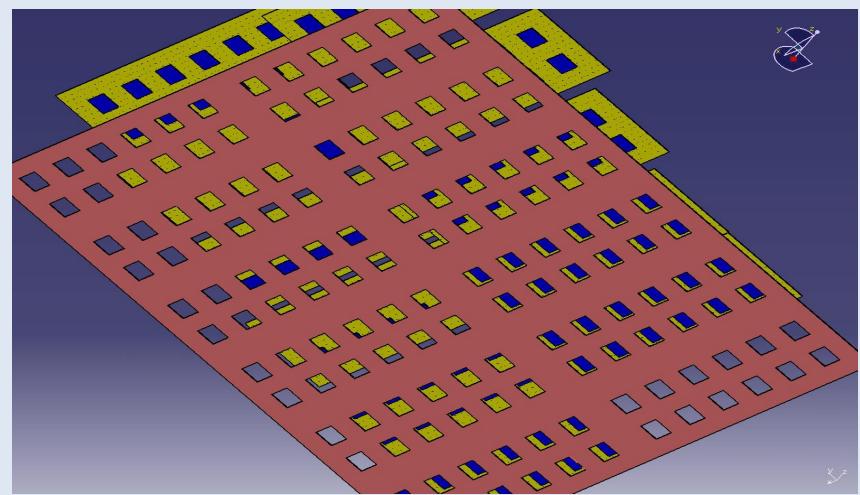
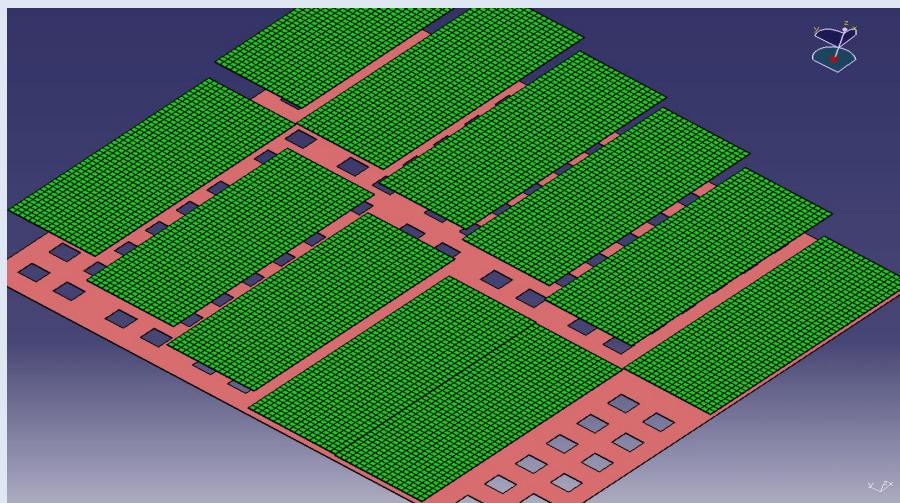
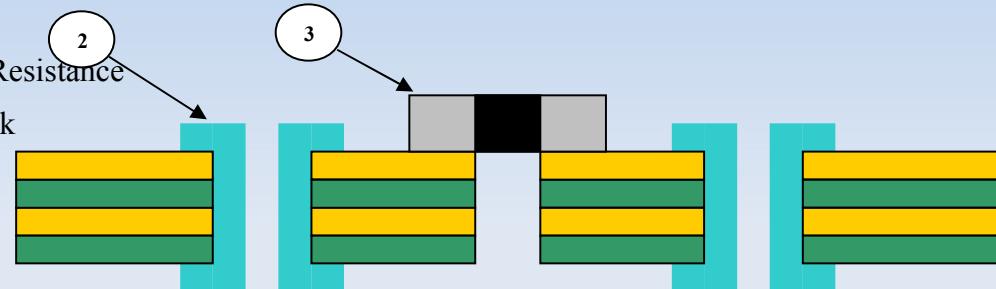
Connection between the different ASU is under study: signal transmission+ mechanics (IPNL+CIEMAT)



Calorimeter for **ILC**



- 1 Weld
- 2 Via
- 3 0 Ω Resistance
- 4 Track



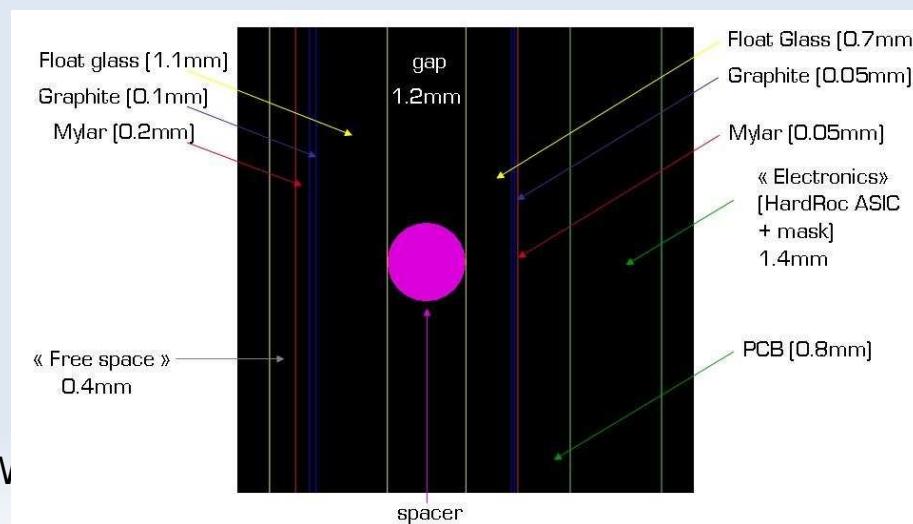
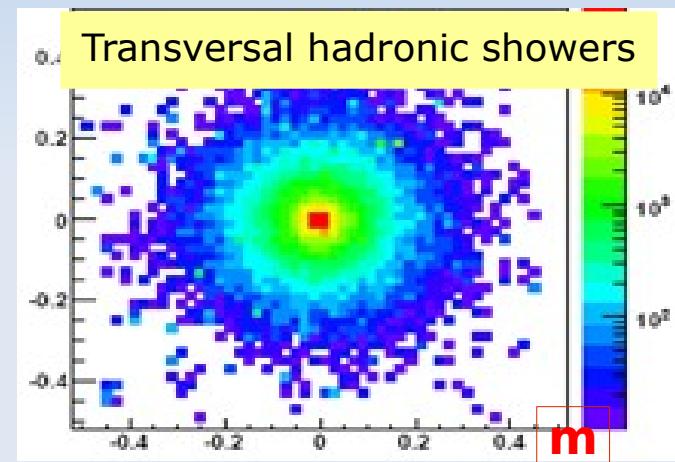
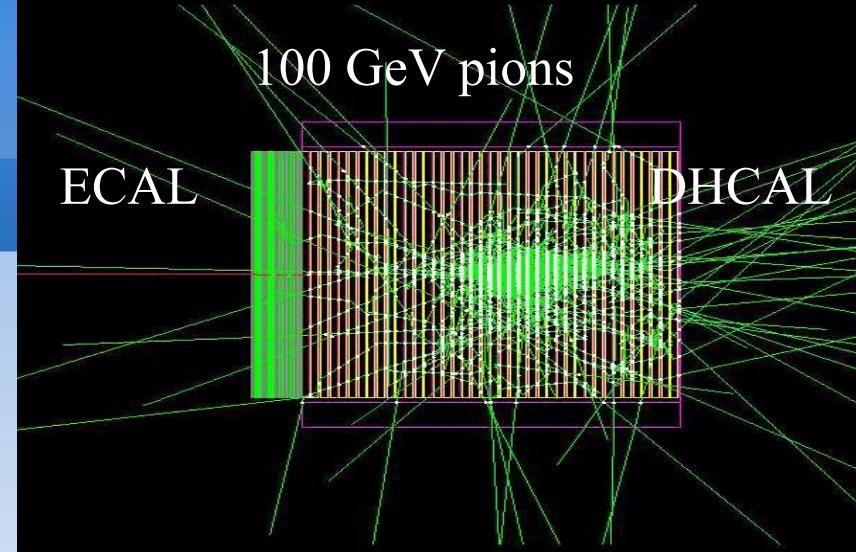
The 1 m³ project

Aims:

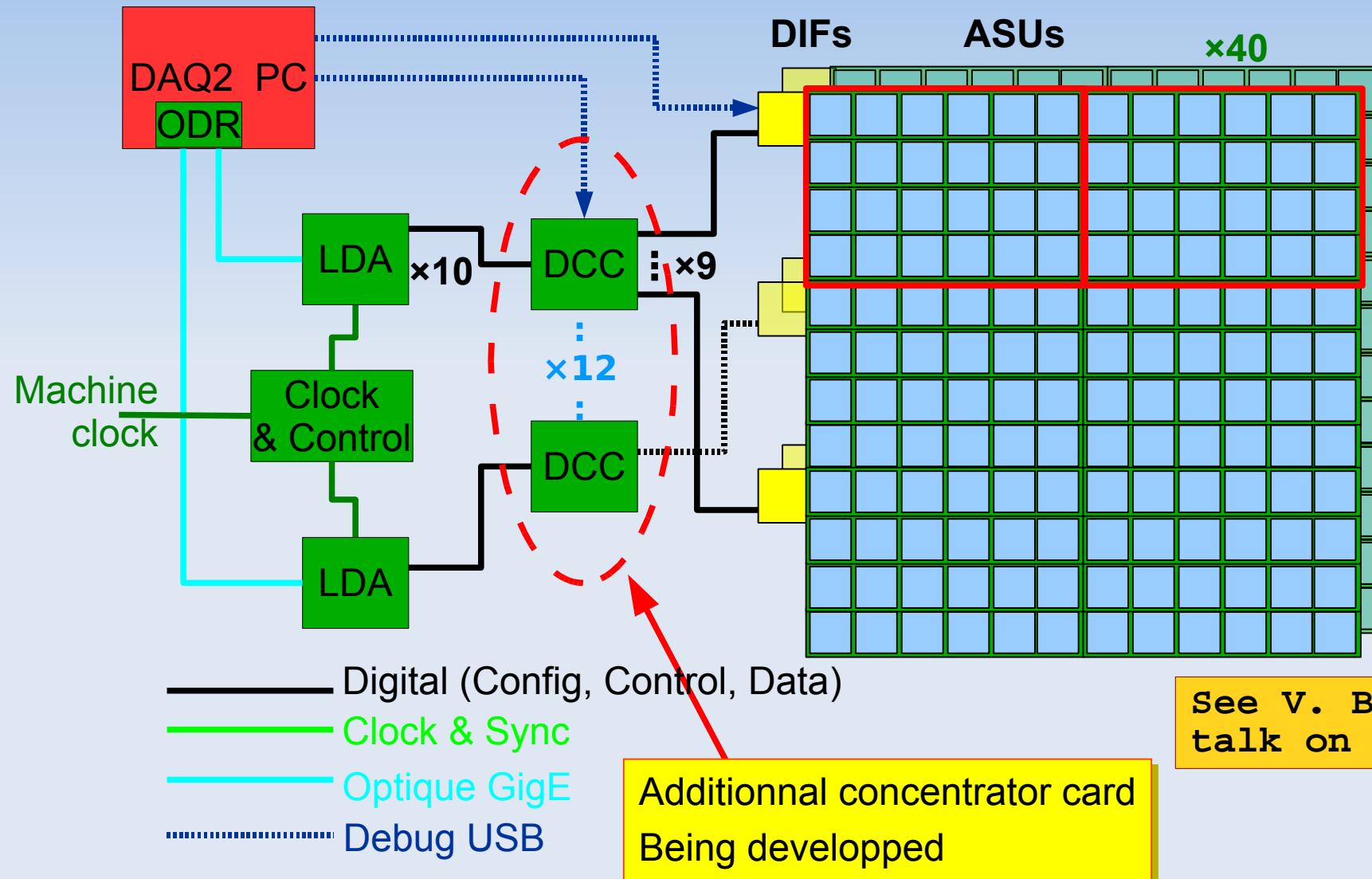
- Demonstrate the Digital SDGHCAL concept
- Learn as much as possible how to build a DHCAL for ILC (technological prototype)
- Study hadronic showers extensively

Implementation:

- ▶ 40 GRPC/ μ Megas interleaved with
- ▶ 40 stainless steel absorbers (2cm thick)
 $\Rightarrow 4.5 \lambda_{\text{had.}}$
- Design optimization is on going using
- GEANT4 with **full cell details**



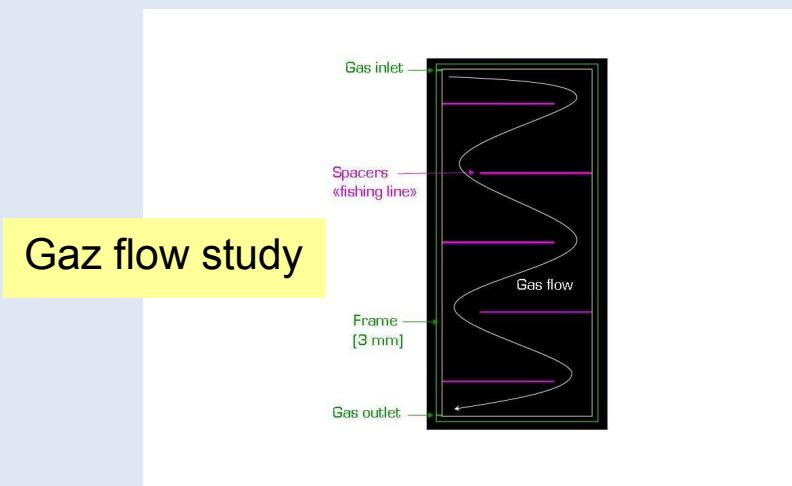
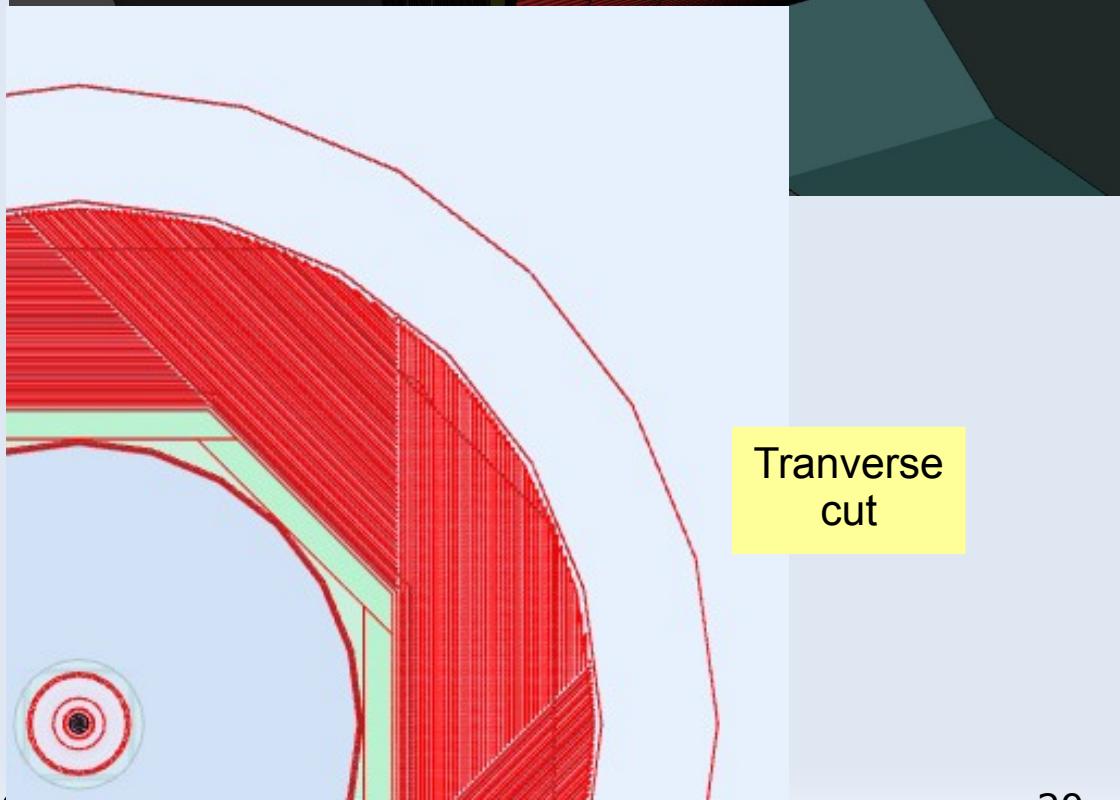
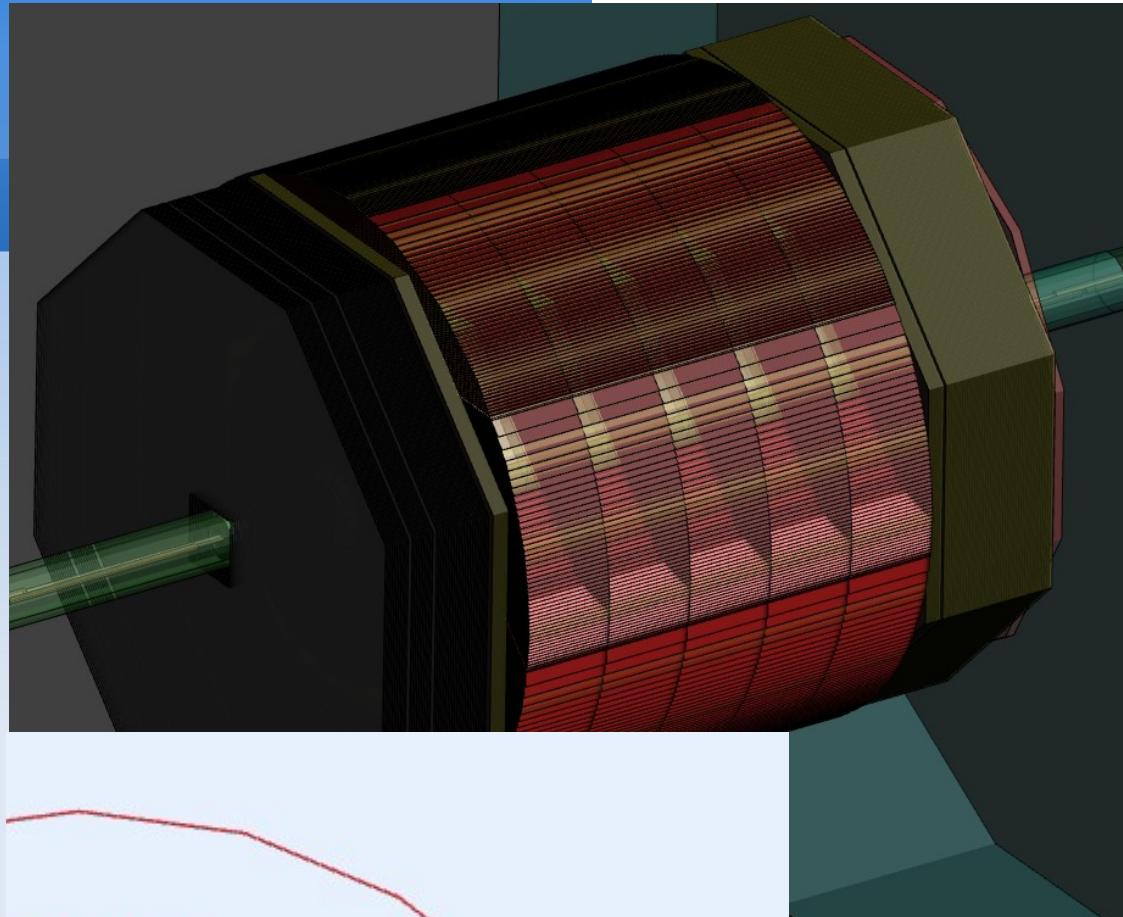
M³: First use of EUDET DAQ2



Reminder: 40×100×100 cells = 400k channels!!!

ILD integration

- Geometry in ILD simulation
 - ▶ 5 wheels + endcaps
 - ▶ 8 Modules/wheel
 - ▶ 48 layers/module
- Electronics, gaz and cooling on the periphery
 - ▶ Jointive barrel & endcaps
- Rigid mechanical structure

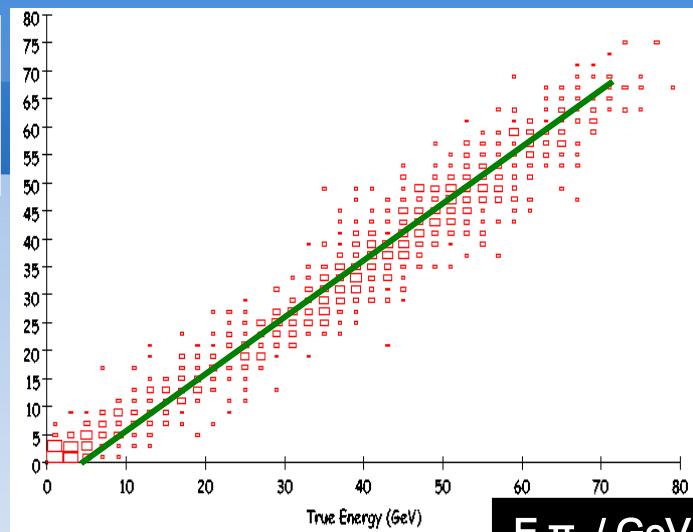


Conclusions & perspectives



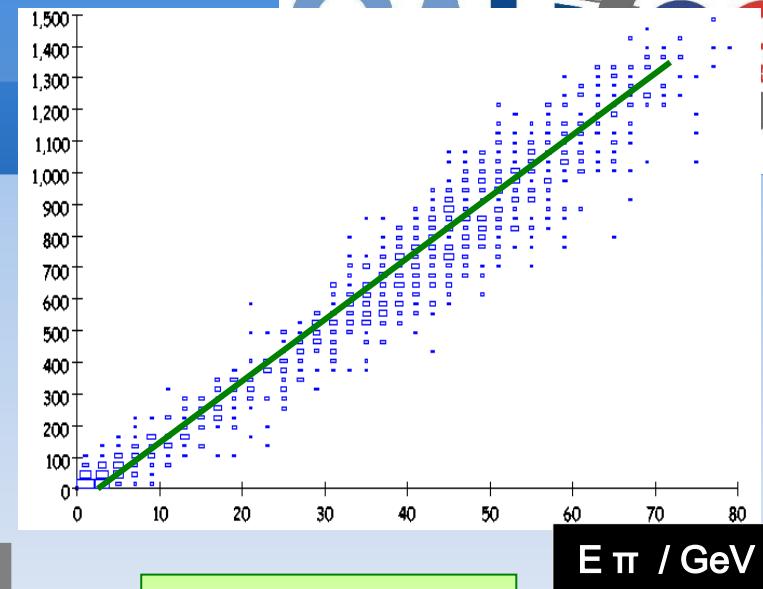
- A Semi-Digital Gaz Hadronic Calorimeter with embedded readout is a very promising candidate for future linear colliders experiments
- A mini SDGHCAL based on first generation readout with GRPC was successfully tested in laboratory and in test beam at CERN
 - ▶ the first results are arriving
- Active development on RPC's and MGRPC
- 1 m² project is ongoing
 - ▶ first equipped 1m² GRPC plan is expected before the end of 2008.
- A technological prototype “1 m³” is funded and expected in 2009-2010

E_{dep}



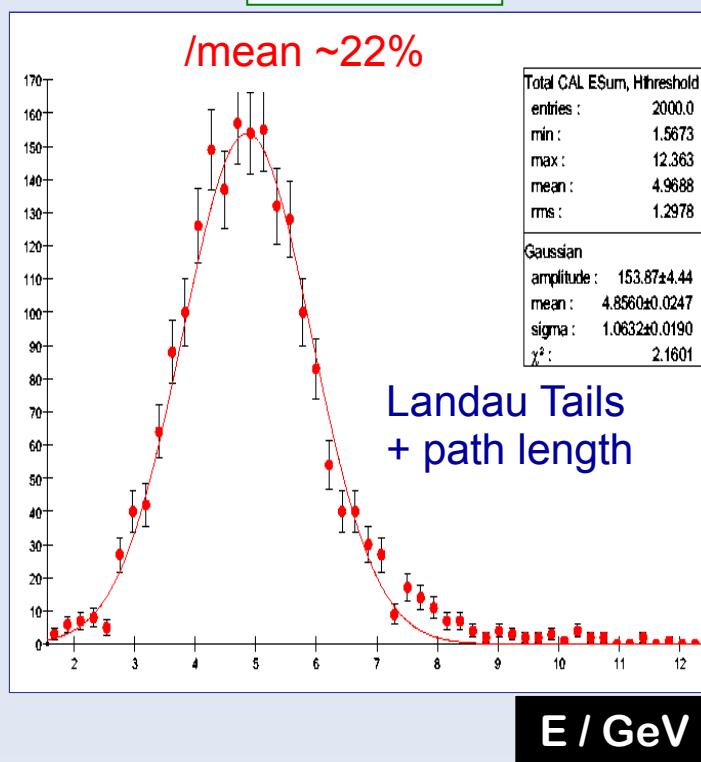
Analog

N hits

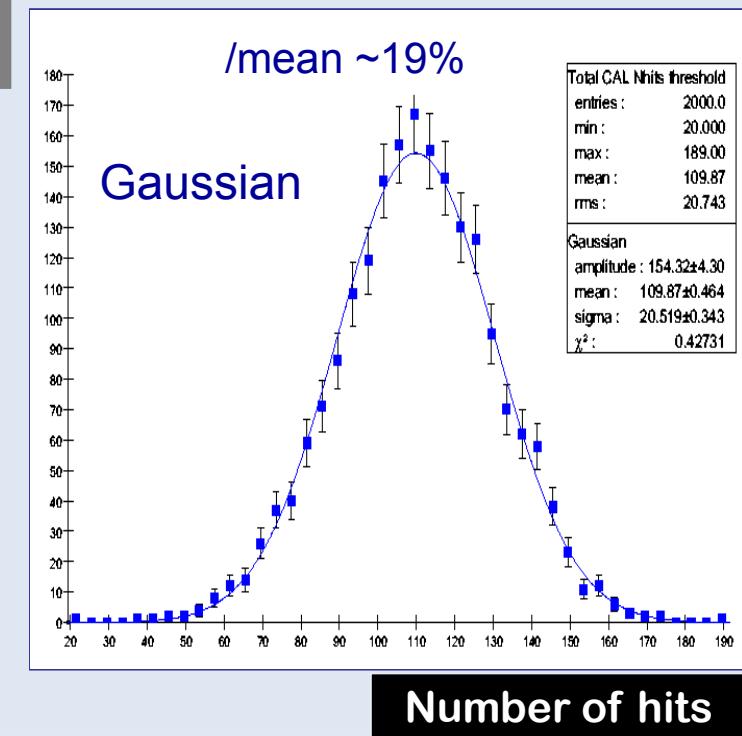


Digital-1bit

Simulation Calice



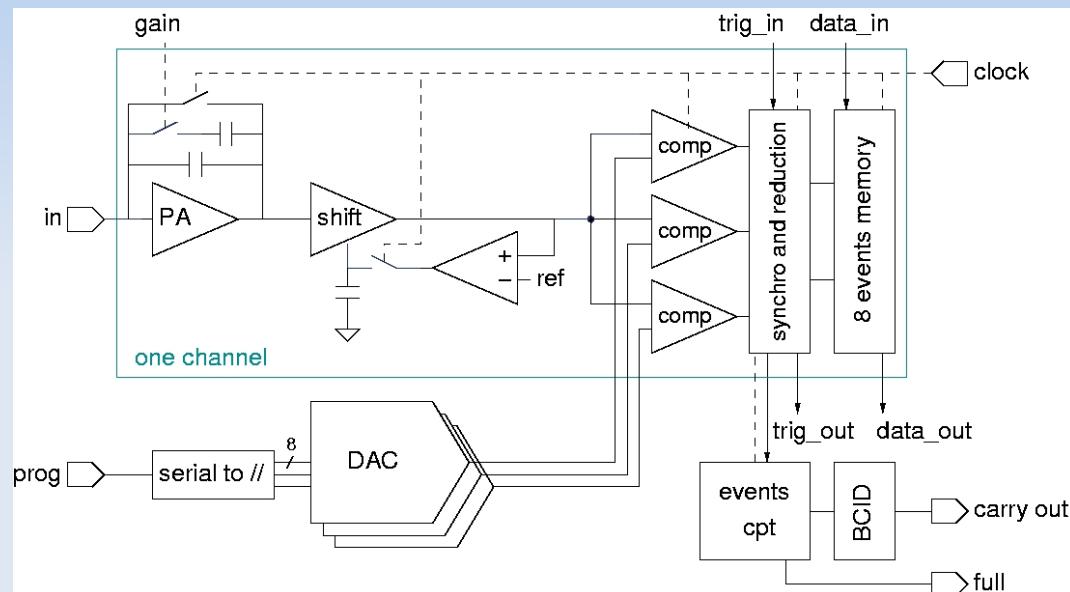
0⁺ 5 GeV



DIRAC ASIC

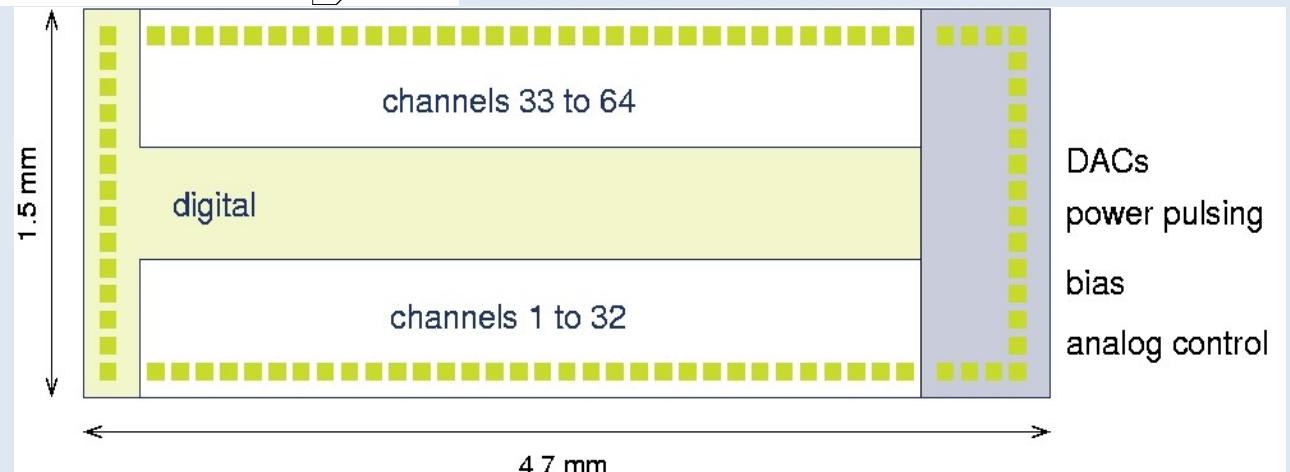


A new chip with a low threshold for μ MEGAS
is under development @IPNL



3 DACs (8 bits each)
BCID = 12 bits
memory depth= 8 evts

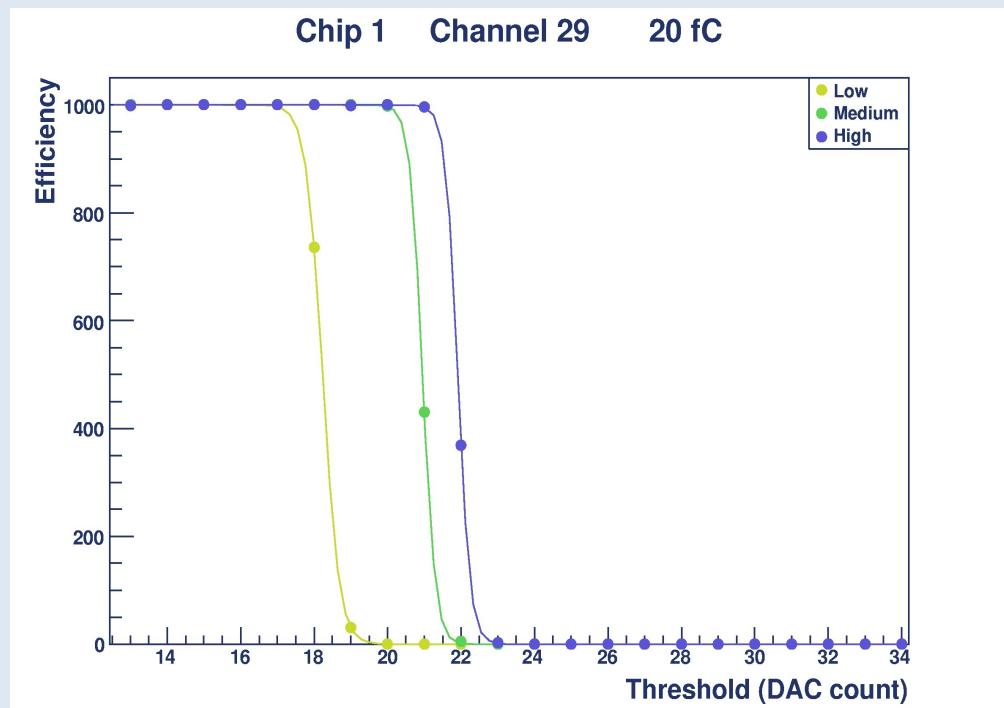
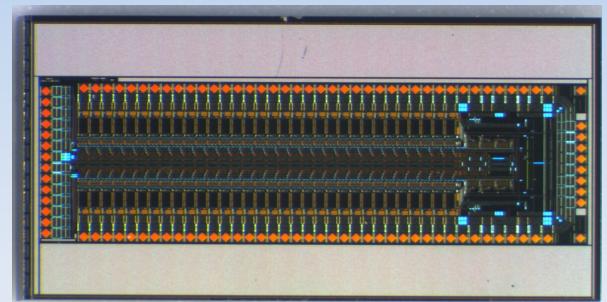
64-ch chip
CMOS tech
power pulsed



Simple geometry



The chip was designed and produced.
A test board using OPERA DAQ
developed @IPNL was used.



First results:
Mode μ MEGAS
0.8 fc/DAQ
Resolution < 2.5 fc

Tests and improvement are going on

HARDROC: Power pulsing

